



Silicon enhancement mode nanostructures for quantum computing

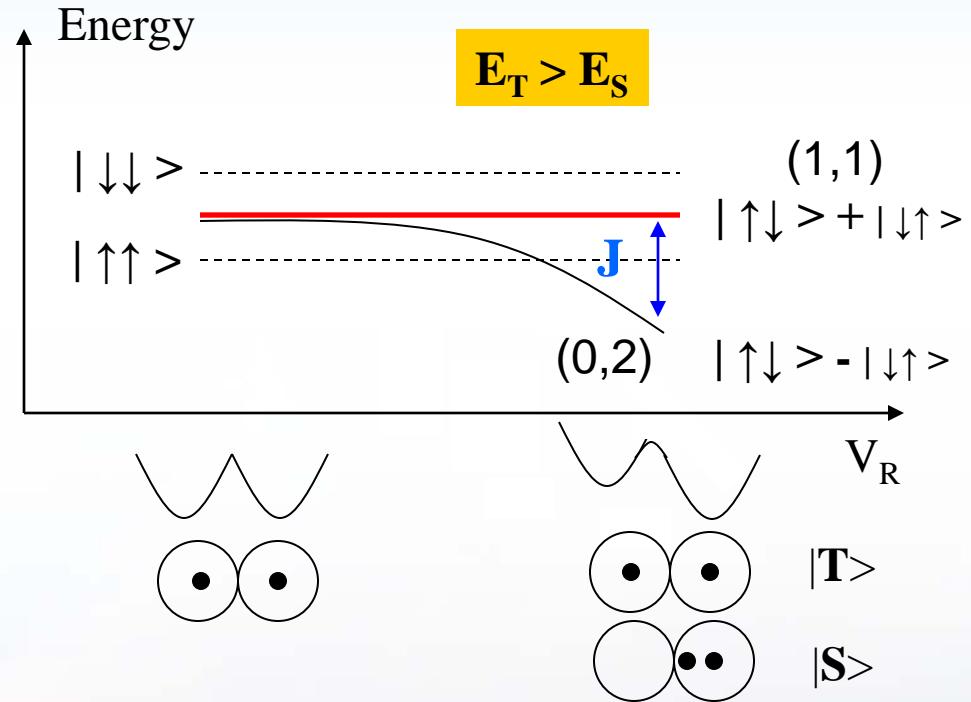
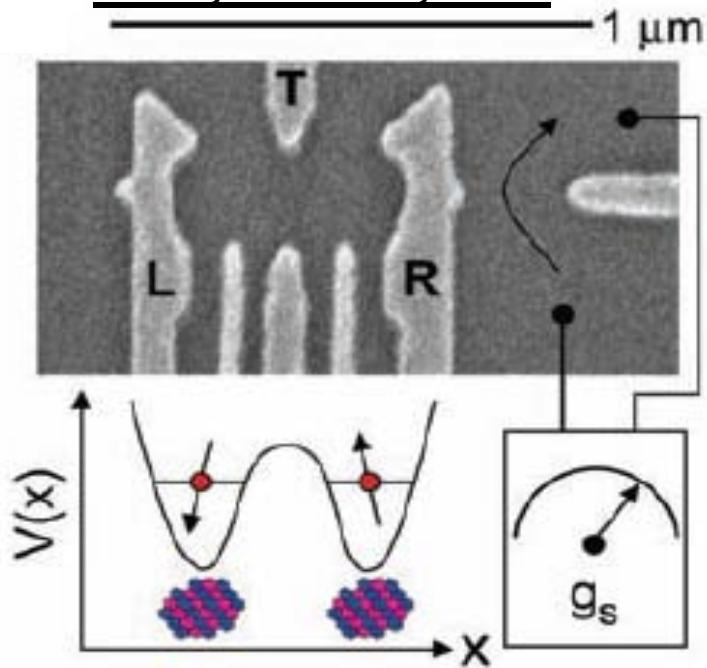
Malcolm Carroll

Sandia National Laboratories
Albuquerque, New Mexico, USA

November 3, 2011

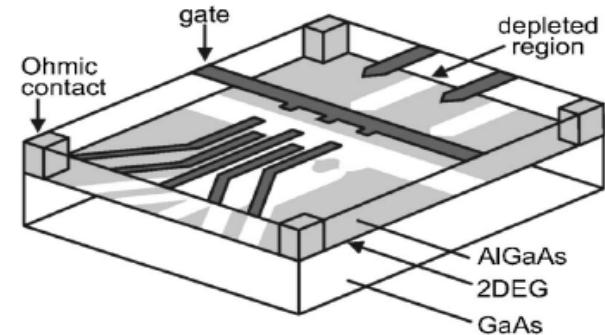
One inspiration for semiconductor quantum computing

Petta, Science, 2005



Elements:

- Two level system
 - $m=0$ subspace of 2 electrons
- Electrically tunable (tunnel coupling)
- Charge sense



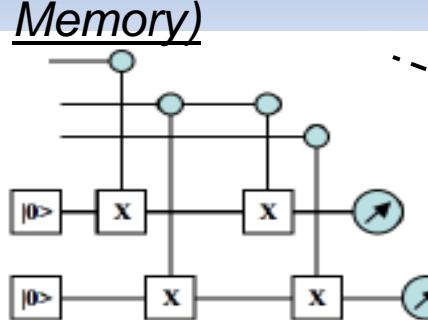


Quantum error correction needed for circuit model approach to QC

Some conclusions from logical memory

- Number of operations necessary to complete a QEC cycle => ballpark 10^{-4}
- Scheduling conflicts lead to more idles and gates (electronics, t_{msr} & DD)
- Circuit would show benefit at $p \sim 5 \times 10^{-4}$ assuming negligible idle error
- You want p/p_{th} as low as possible to reduce amount of QEC
- Fast high fidelity gates is made difficult in system (e.g., jitter on MUX/DEMUX clock)
- Long T2 really helps both idle as well as minimizing error in gates w/out DCG

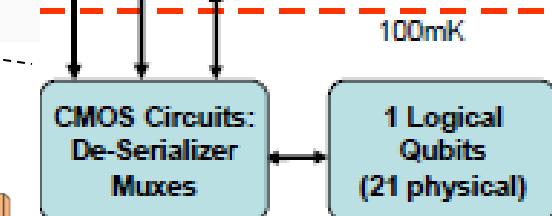
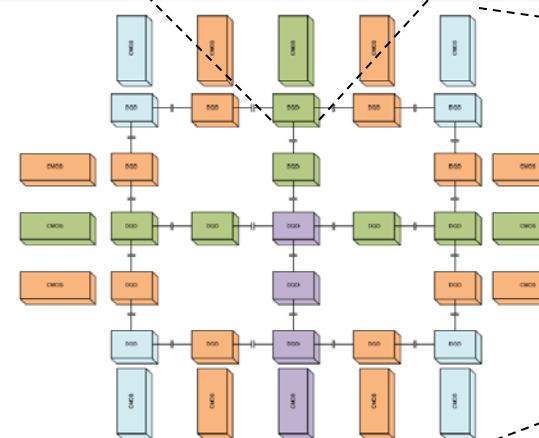
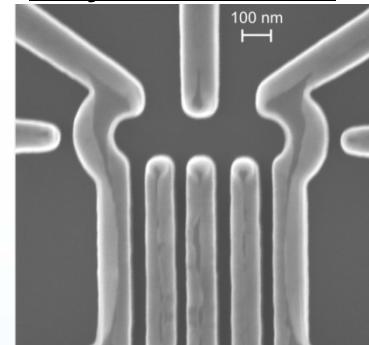
Quantum Circuit (Logical Memory)



Classical-Quantum Interface



Physical Qubit

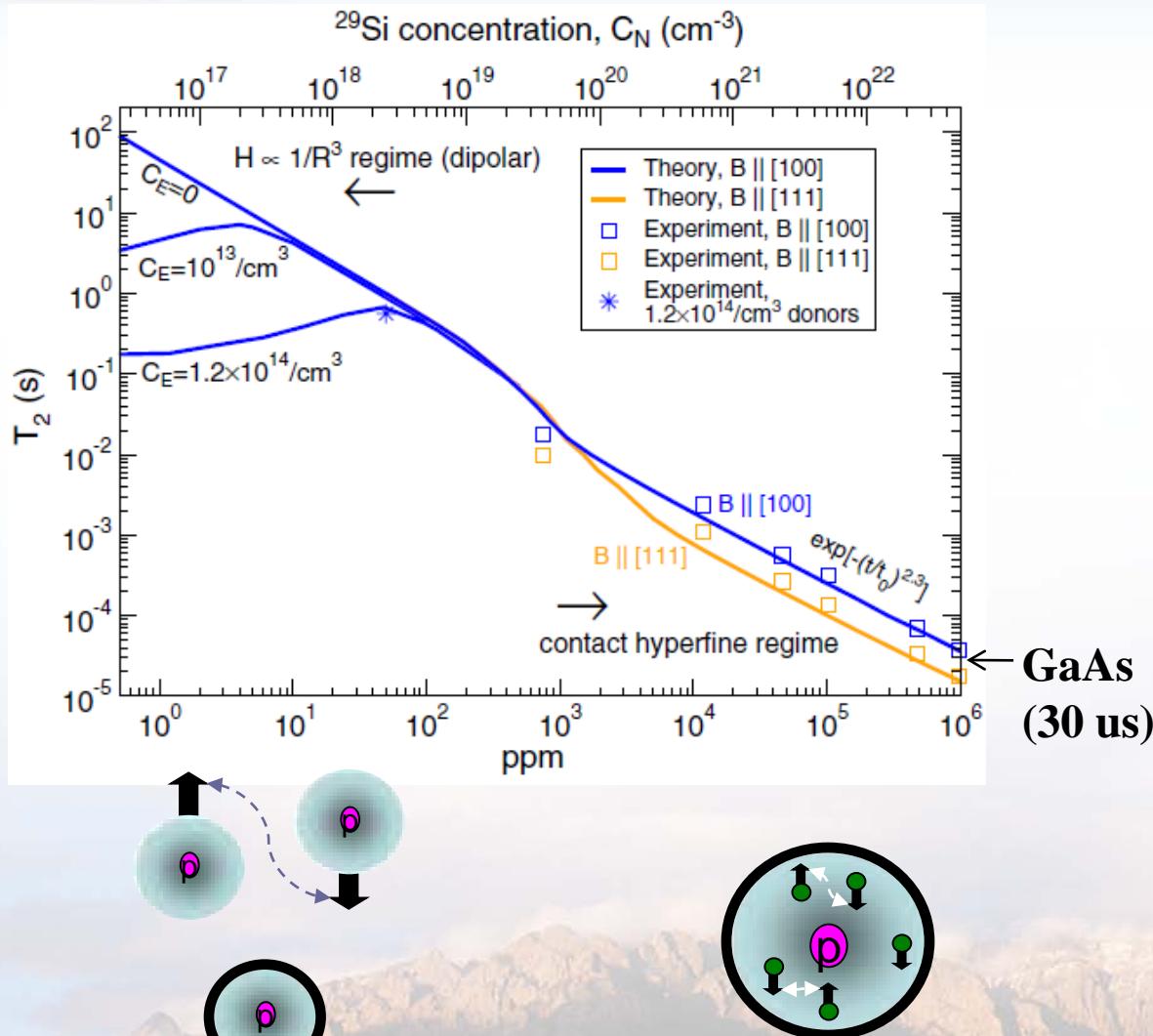


Chip Level Circuit (21 qubits)



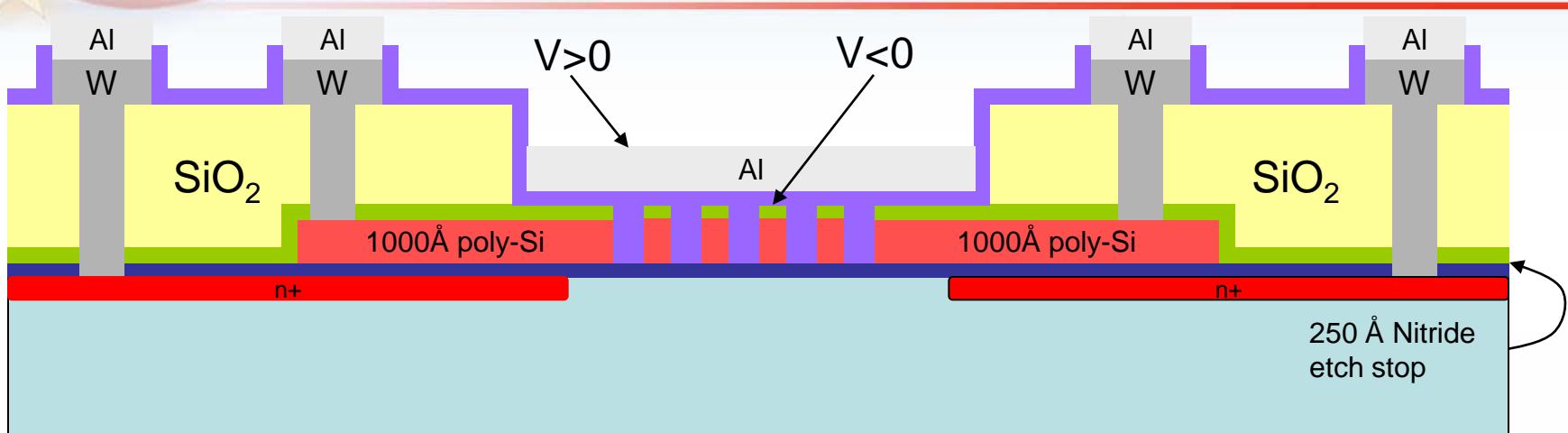
Sandia National Laboratories

Motivation for Silicon Qubits



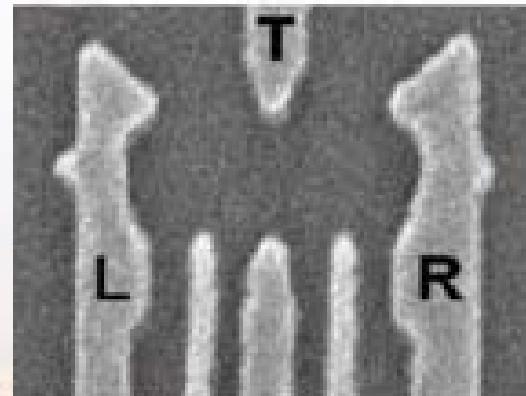
- GaAs has non-zero nuclear spin isotopes shorten T_2
- Si isotope enrichment removes nuclear spin, long T_2
- Nuclear spins can be useful for rotations between S & T0 but it limits T_2 , introduces errors on other gates
- Recent device progress in electron spin manipulation (spin read-out & evidence of coherence)
 - UNSW (donors)
 - UCLA (MOS)
 - HRL (SiGe mod. doped)
 - U. Wisconsin (SiGe mod. doped)

Silicon Enhancement Mode Quantum Dots



- Many silicon approaches
- SNL looking at enhancement mode & Si foundry approach
- This talk: MOS, SiGe/sSi and donors

GaAs design to Si?



Motivations

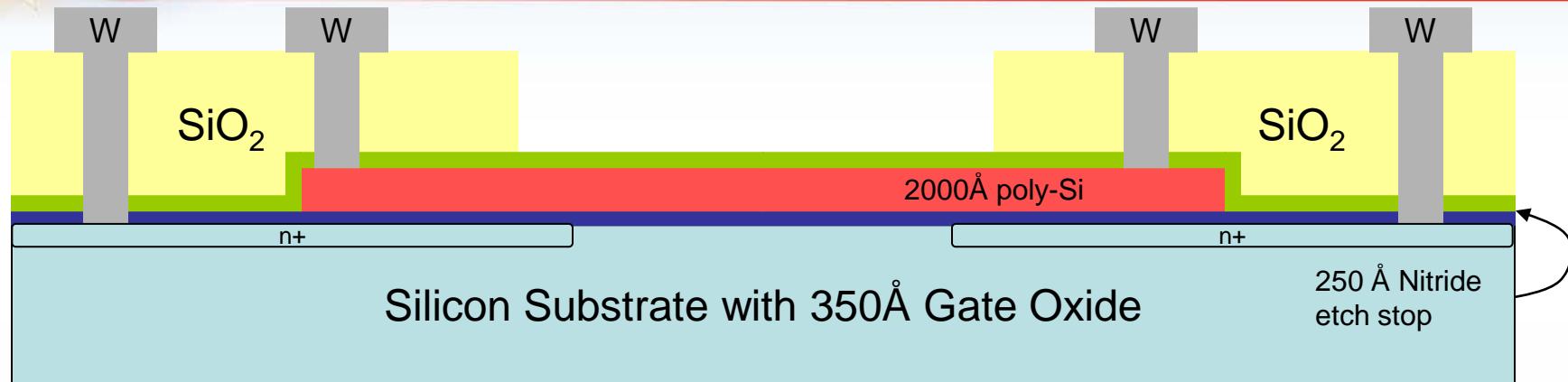
1. Platform is modular design for both donors and SiGe/sSi
2. Tunable parameters (density, valley splitting, g-factor?)
3. No dopants
4. Start with MOS:
 - well understood material system
 - overlapped interests for other Si approaches
5. CMOS compatible (MOS)

Petta et al. [2005]



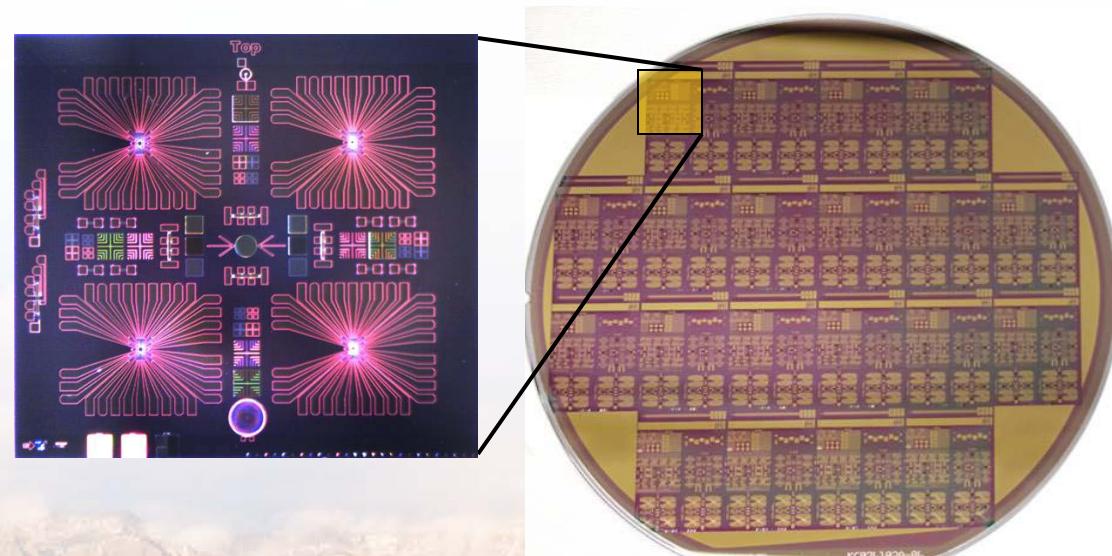
Sandia National Laboratories

Silicon foundry



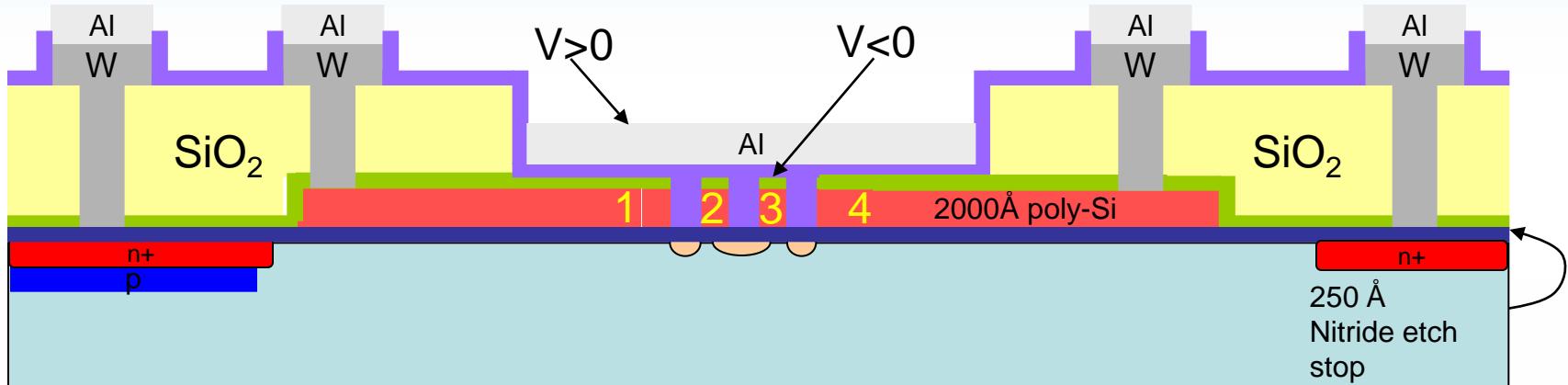
MOS Stack from Si fab

Deep UV lithography (0.18 um)
7,500 – 15,000 mobility cm²/Vs
QDs possible with 0.18 um litho
Smaller features w/ EBL in/out of fab
Standard MOS material set only

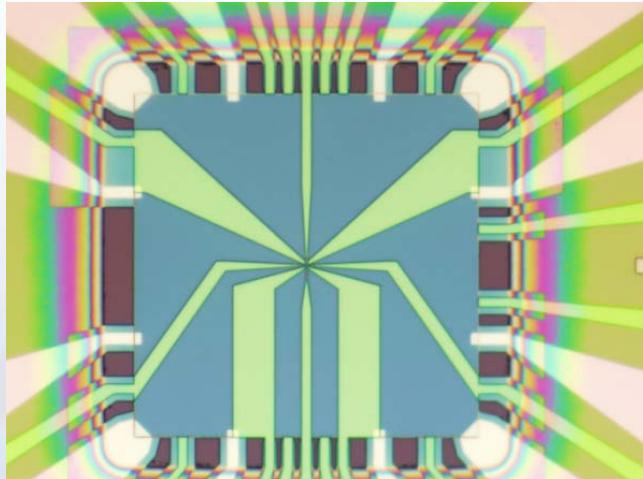


Sandia National Laboratories
T. Pluym

Back-end processing



GaAs design to Si



Micro-fab facility

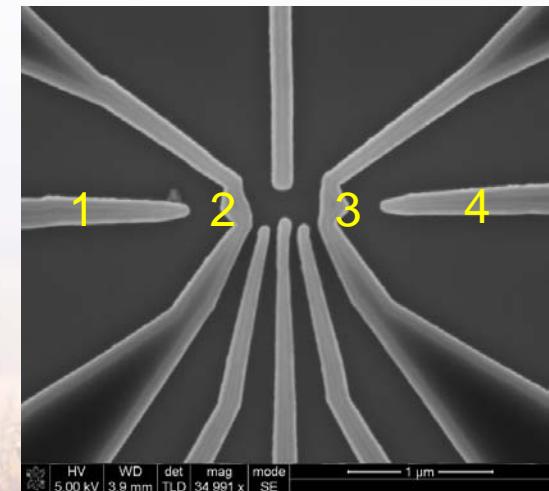
Rapid turn-around EBL

Poly-silicon etch

Aluminum oxide

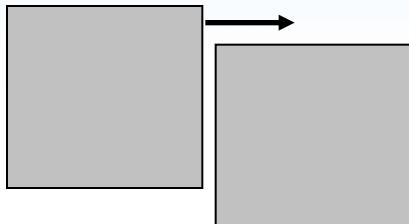
Top Al gate

Low parasitic RF die

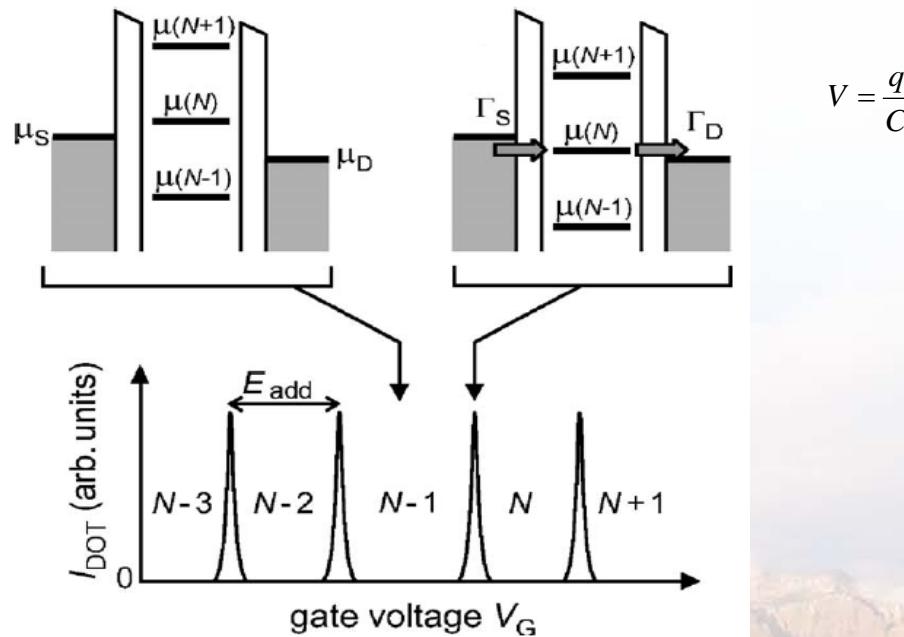


Coulomb blockade

Imbalance in chemical potential produces current



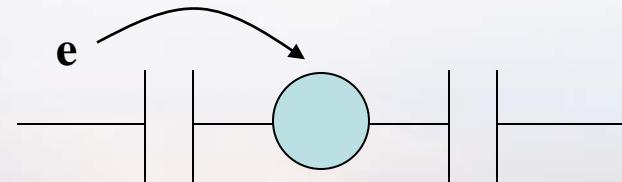
- Equally spaced energy levels related to charging energy of capacitance
- Periodic current resonances produces – “Coulomb blockade”
- Low temperatures required ($T \ll 4K$)



$$V = \frac{q}{C}$$

$$C_{\text{sum}} \sim 16 \text{ aF}$$

$$\Delta V = \frac{q}{C} \sim 1 \text{ mV}$$

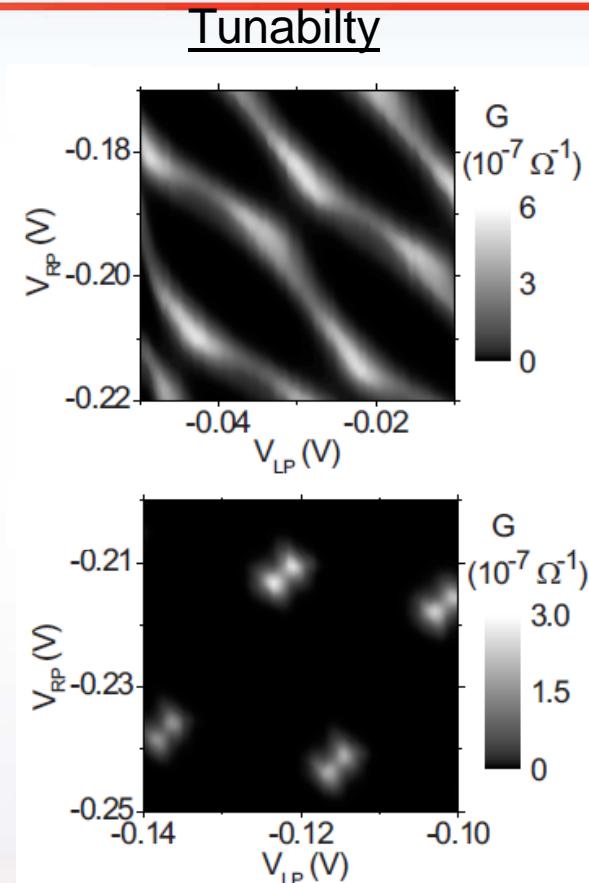
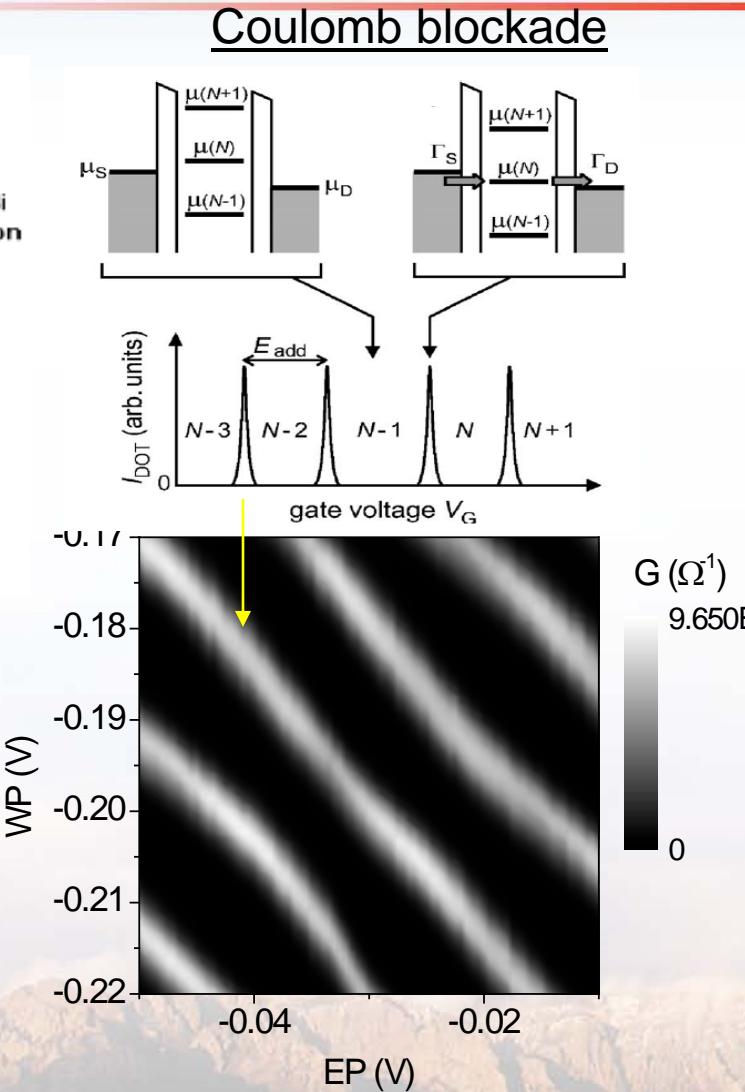
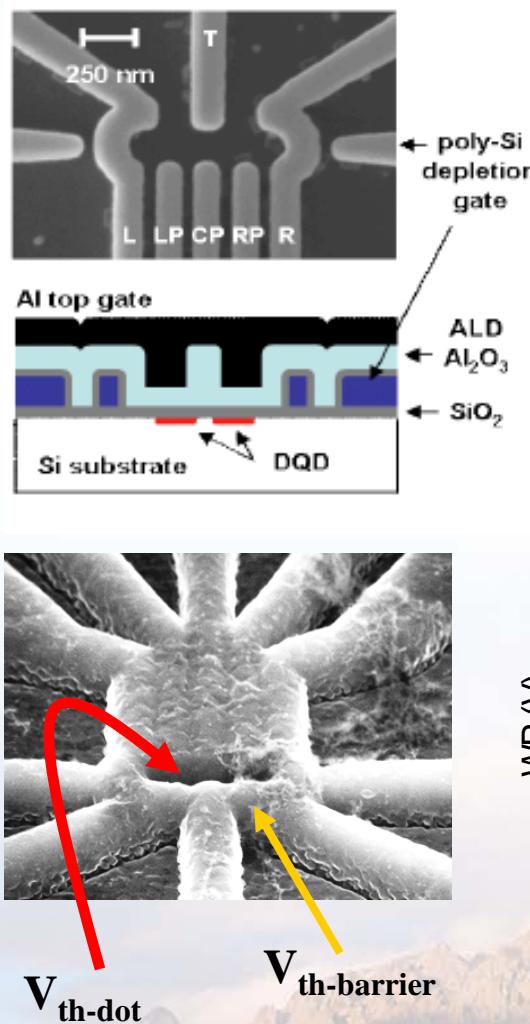


Chemical potential levels are spaced by charging energy



Sandia National Laboratories

Reconfigurable Dot with Gates

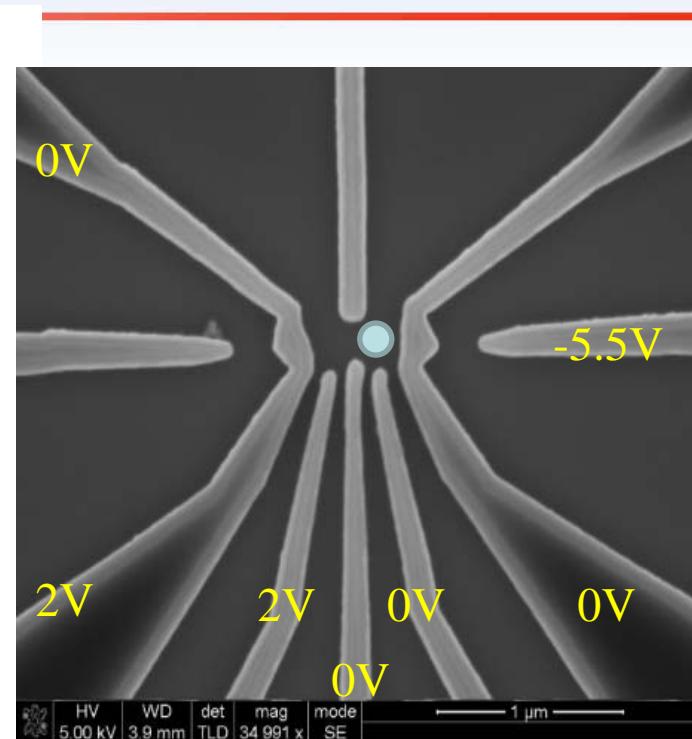
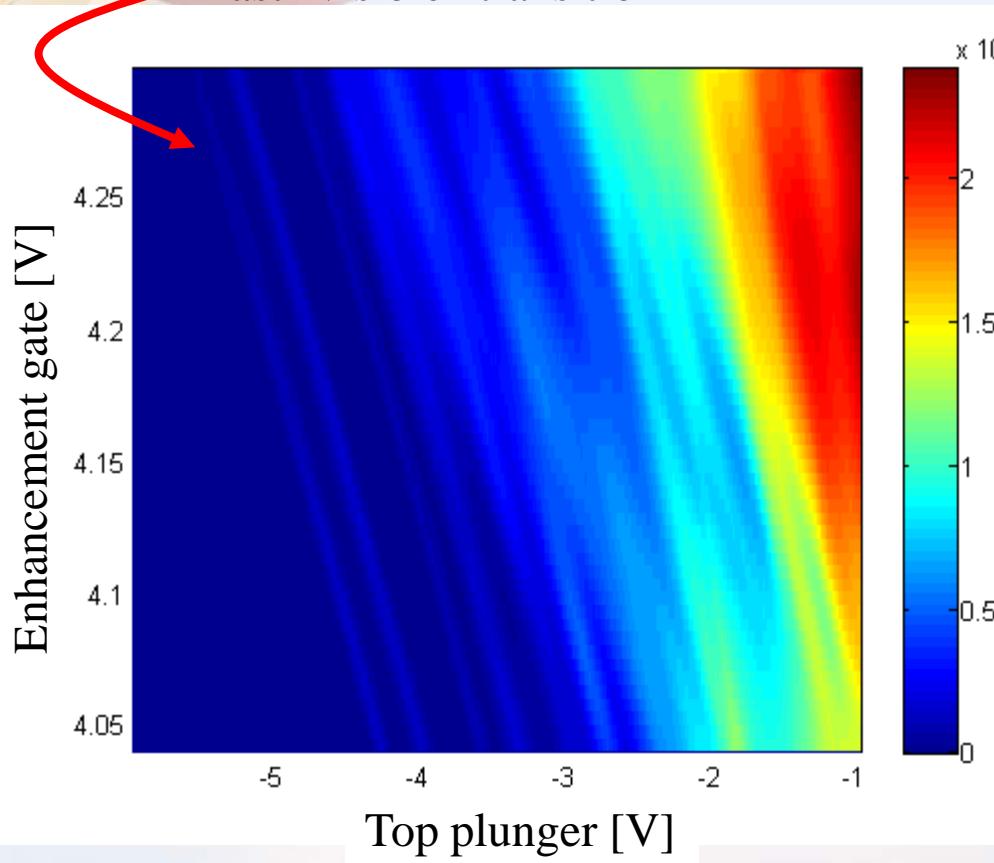


Problems:

1. Charge sensor constriction too thin
2. Top gate coupling imbalance to barrier/dot

Few electron single QD

Last “visible” transition



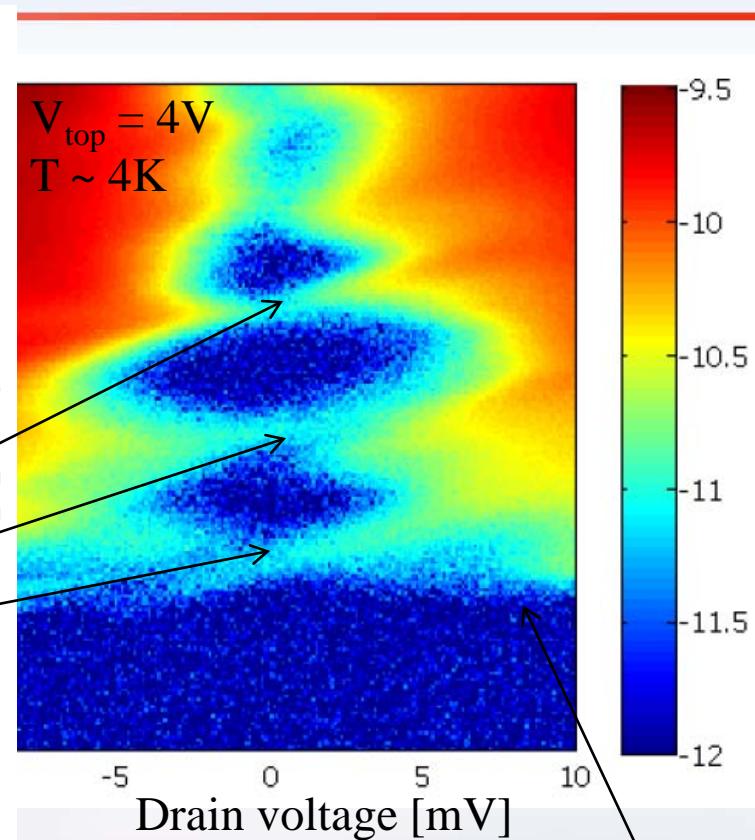
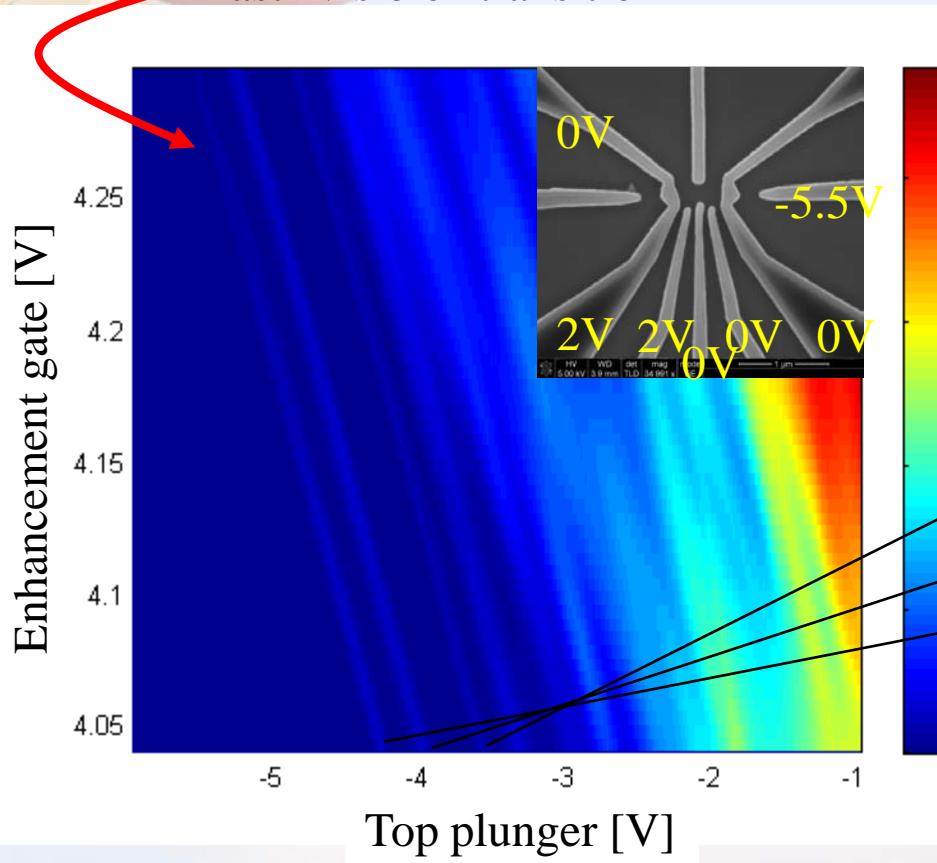
- Edge of transport through dot observed
- Several possible reasons
 - tunnel barrier is gradually turning off (often the case)
 - Last electron
- This case is not gradual and no additional transitions are observed over reasonably large V_{top} scan and V_{sd}



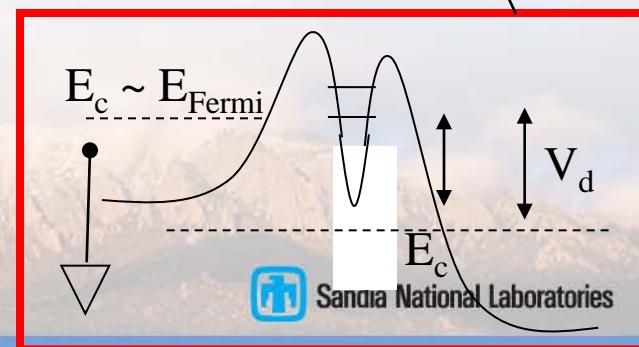
Sandia National Laboratories

Wider tunnel barrier

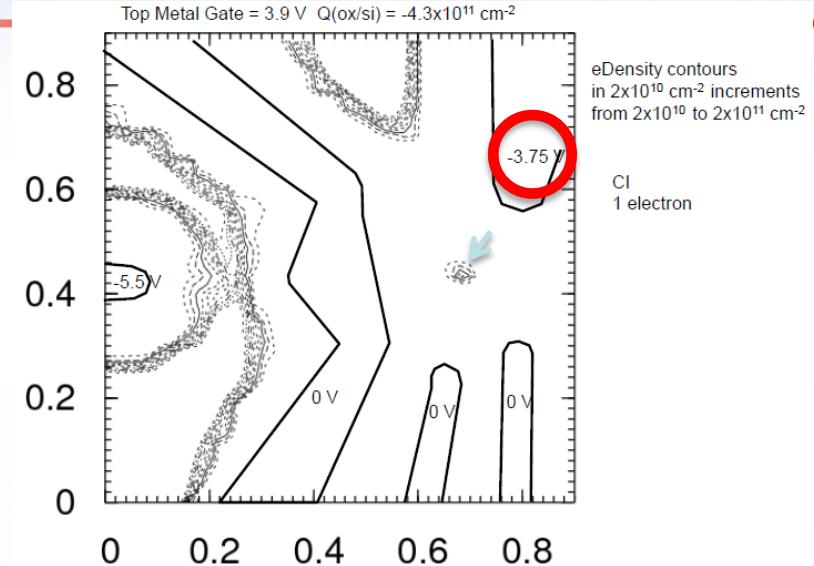
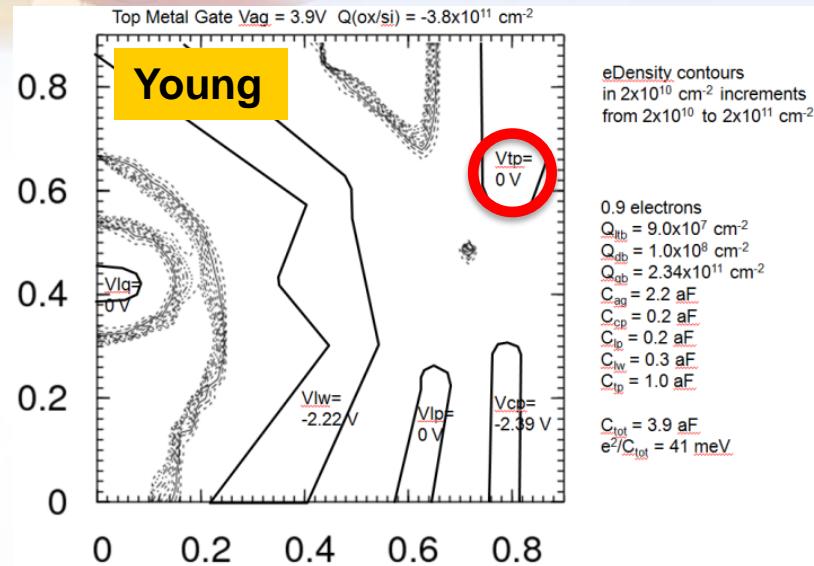
Last “visible” transition



- Edge of transport through dot observed
- Several possible reasons
 - tunnel barrier is gradually turning off (often the case)
 - Last electron
- This case is not gradual and no additional transitions are observed over reasonably large V_{top} scan and V_{sd}



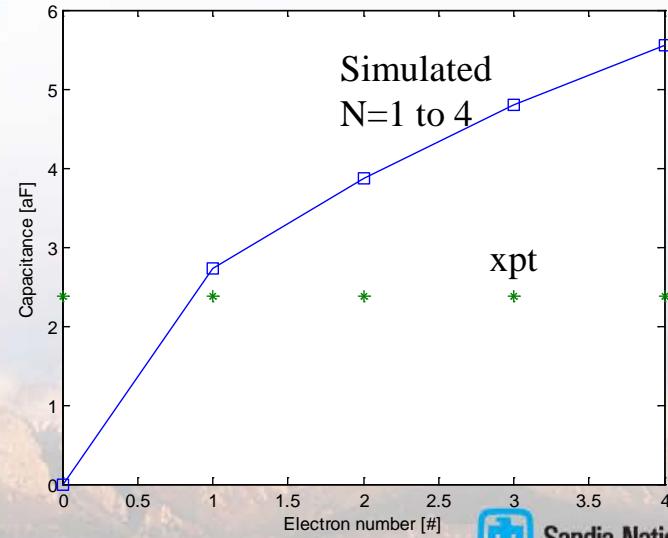
Simulation calibration



Gate	Measured [aF]	CI (N=1) [aF]	Semi-classical [aF]
		TP=-3.75/ 0	TP=-3.75
AG	2.37	2.73 / 2.2	3.13
TP	0.48	0.29 / 1.0	0.3
L	0.56	1.56 / 0.3	1.9
LP	0.29	0.45 / 0.2	0.49
CP	0.54	0.59 / 0.2	0.66

Carroll, Young

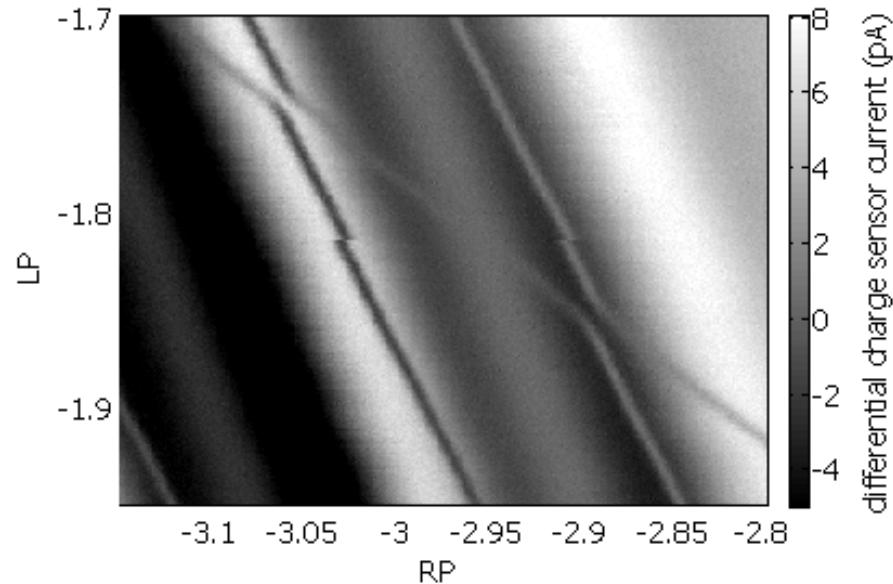
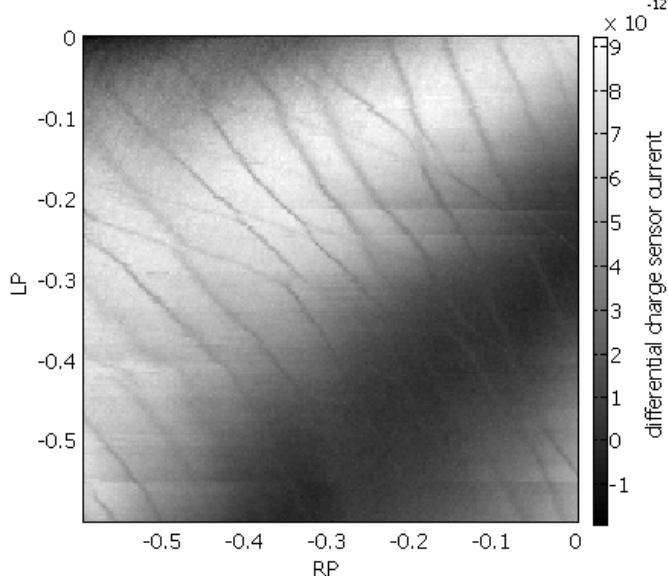
- Simulation is consistent with observed magnitudes in experiment at N=1



Sandia National Laboratories

Double dot and charge sensing

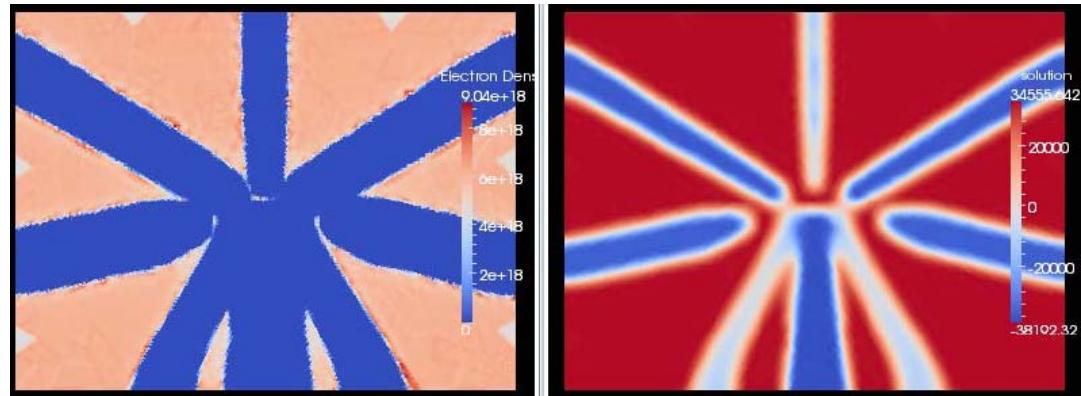
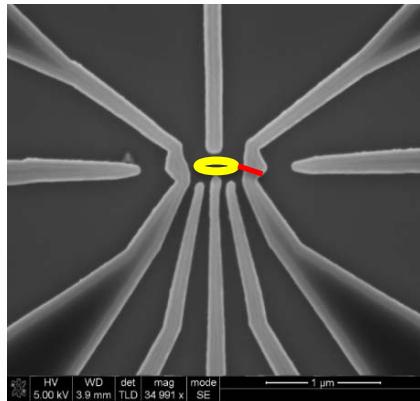
MOS (same device as before)



- Primary concern is to isolate a singlet and T0 subspace for qubit => tune DQDs
- Beginning to look for Pauli-blockade in many electron cases and few electron when possible
- Challenges:
 - Sensitivity
 - Reduce chance of defects
 - Fewer electrons
 - => smaller size designs

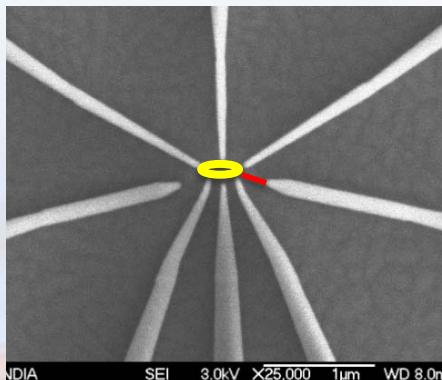
Smaller dot designs and path dependent tunability

Modeling optimization: few electron DQD possible

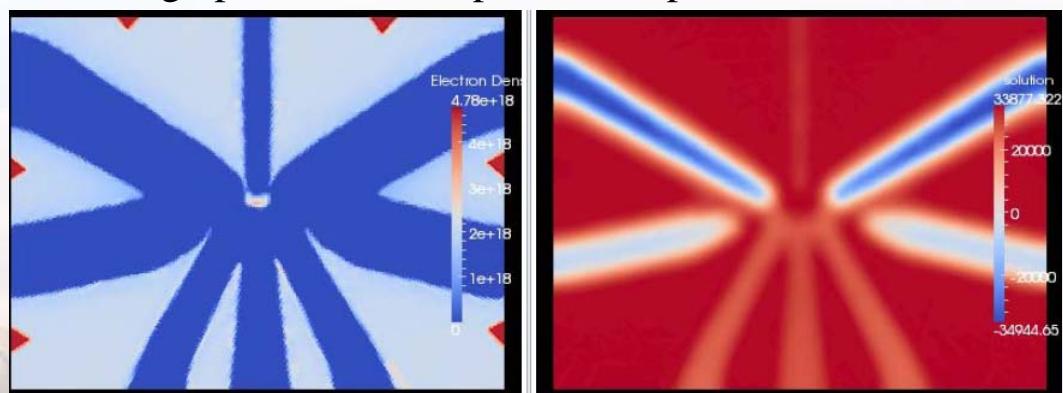


Smaller dot size & proximity

1. Better charge sensitivity
2. Fewer defects



Modeling optimization: experimental path has non-ideal minima



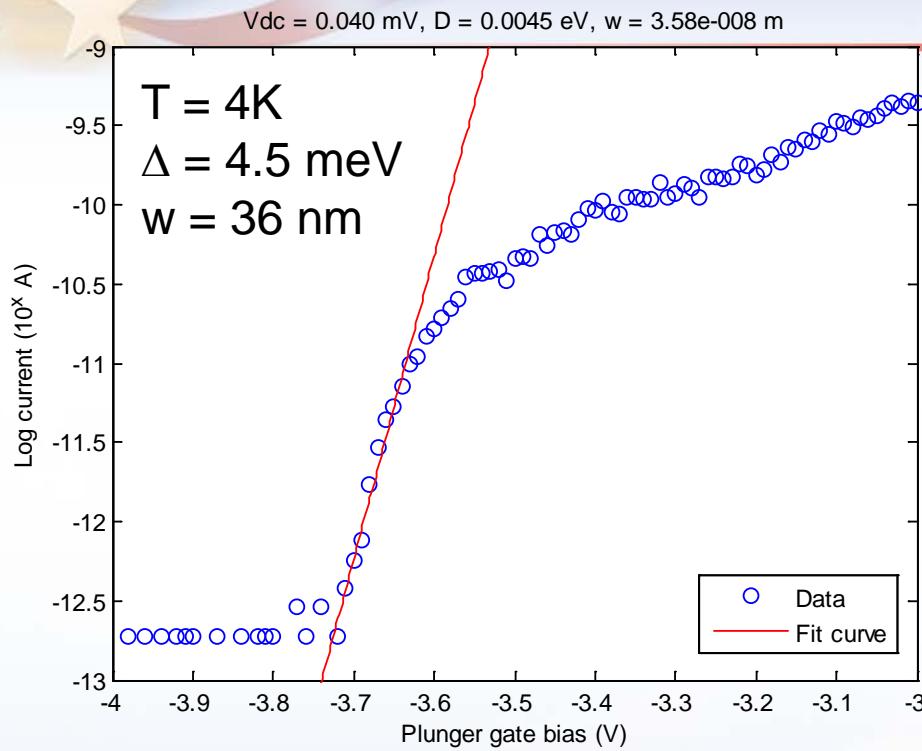
Nielsen, Muller, Young (synergistic research)

Bishop

Sandia National Laboratories



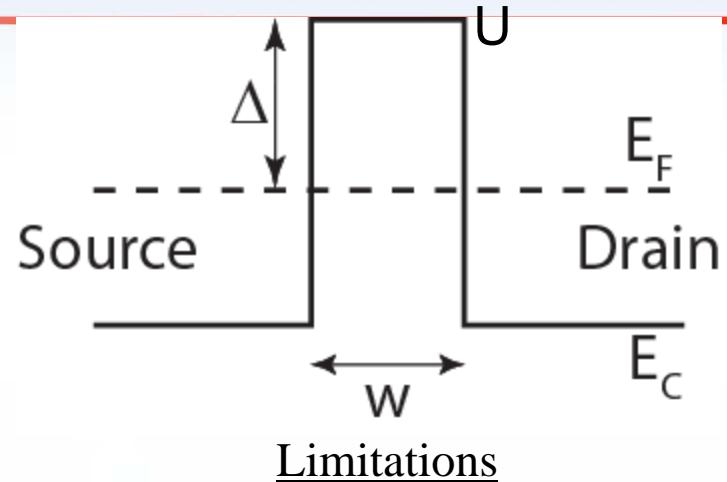
Tunnel barrier model



$$I = q\Gamma \approx f_0 e^{-\frac{2w}{\hbar}\sqrt{2m^*\Delta}}$$

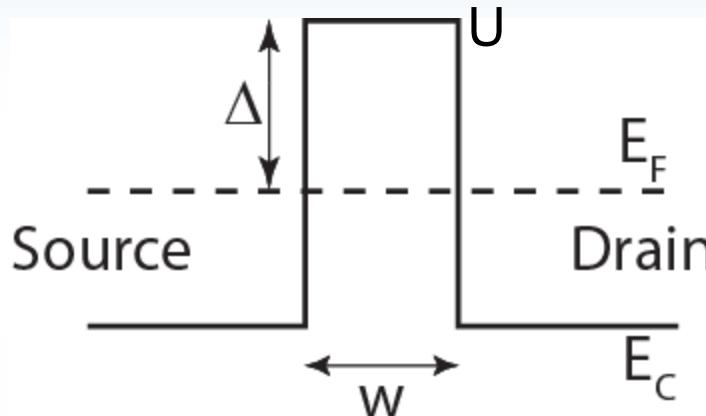
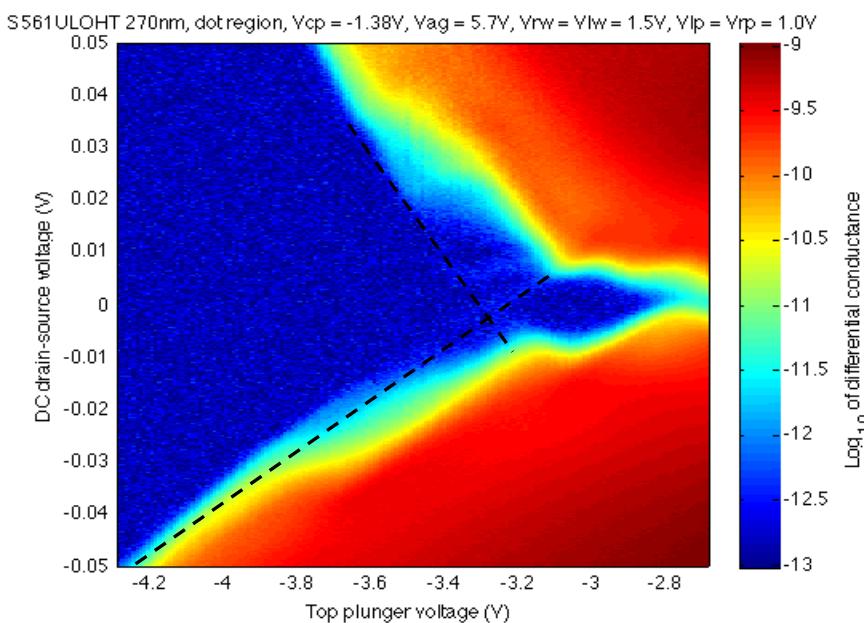
$$\ln(I) = \ln(qf_0) - \frac{w}{\hbar}\sqrt{\frac{2m^*}{\Delta}} \left(2\Delta + q\frac{C_{gate}}{C_\Sigma}(V_0 - V) \right)$$

$$y = mx + b$$



- Square barrier
- WKB approximation
- Linearize the radical
- Phenomenological parameter f_0

Consistent results

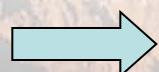


Non-zero V_{sd}

V_{ds} (mV)	V_g (V)	Δ (meV)	W (nm)	$\Delta @$ $V_{ds} = 0V$ $V_g = -3.4V$ (meV)
-11	-3.26	4.63	21.9	15.6
-10	-3.24	4.42	22.9	13.7
10	-3.12	2.79	26.8	13.8
11	-3.13	2.69	26.7	13.7

$$dU = \frac{\partial U}{\partial V_{sd}} dV_{sd} + \frac{\partial U}{\partial V_{gate}} dV_{gate}$$

$$dU = \Delta - \Delta_0 - q|V_{sd}|$$

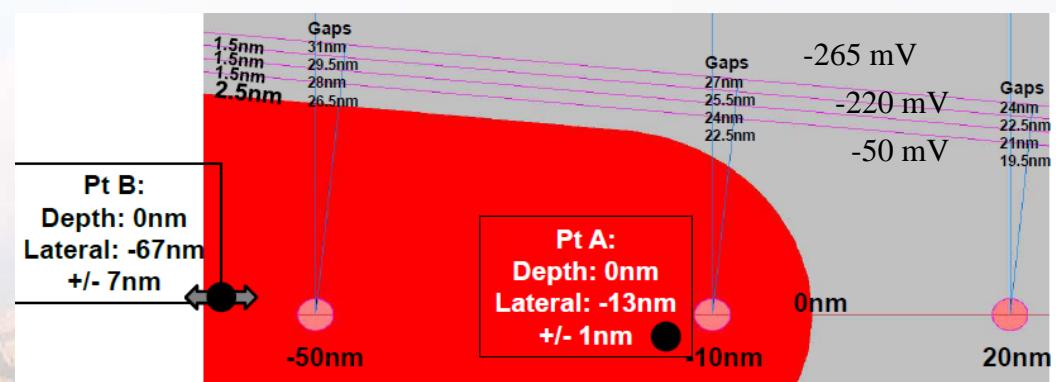
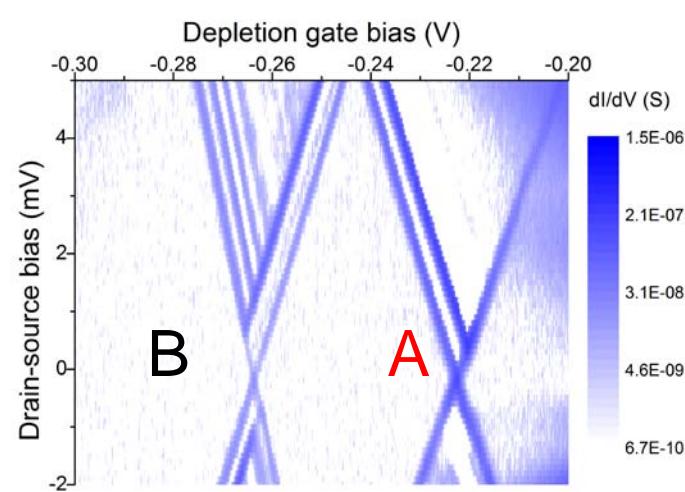
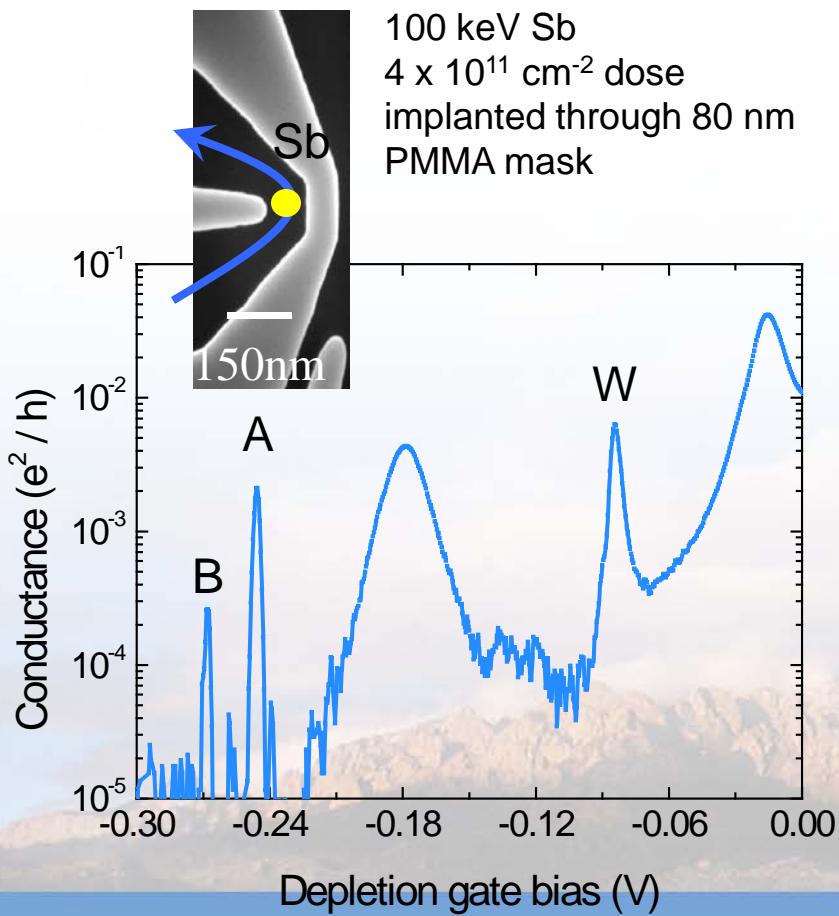
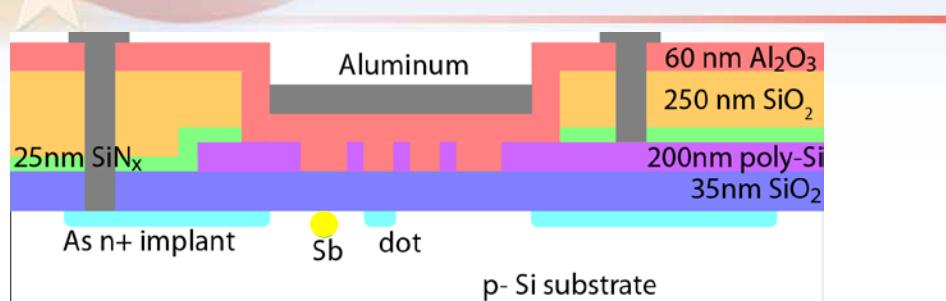


$$\Delta = \Delta_0 + q|V_{sd}| + \frac{C_S}{C_\Sigma} dV_{sd} + \frac{C_G}{C_\Sigma} dV_{gate}$$



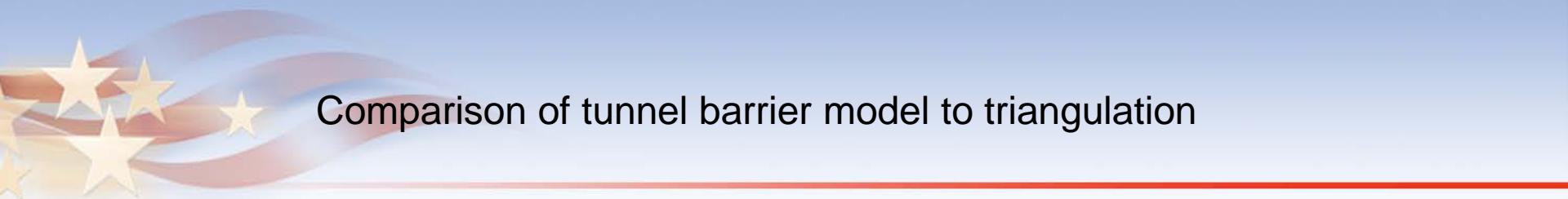
Sandia National Laboratories

Triangulation of resonances in implanted split-gates



Sandia Nation

Bishop



Comparison of tunnel barrier model to triangulation

Resonance B

V _{sd} (mV)	V _g (V)	Δ (meV)	W (nm)
25	-0.3805	2.21	48.4
22	-0.3745	2.53	45.6

Resonance A

V _{sd} (mV)	V _g (V)	Δ (meV)	W (nm)
25	-0.353	1.65	39.1
22	-0.345	1.82	38.6

For V_{SD} = 0V and V_g = -0.27V, Δ = 9.12 meV

dU/dV_{SD} = -0.4203 eV/V (C_s/C = 0.4468)

For V_{SD} = 0V and V_g = -0.24V, Δ = 6.05 meV

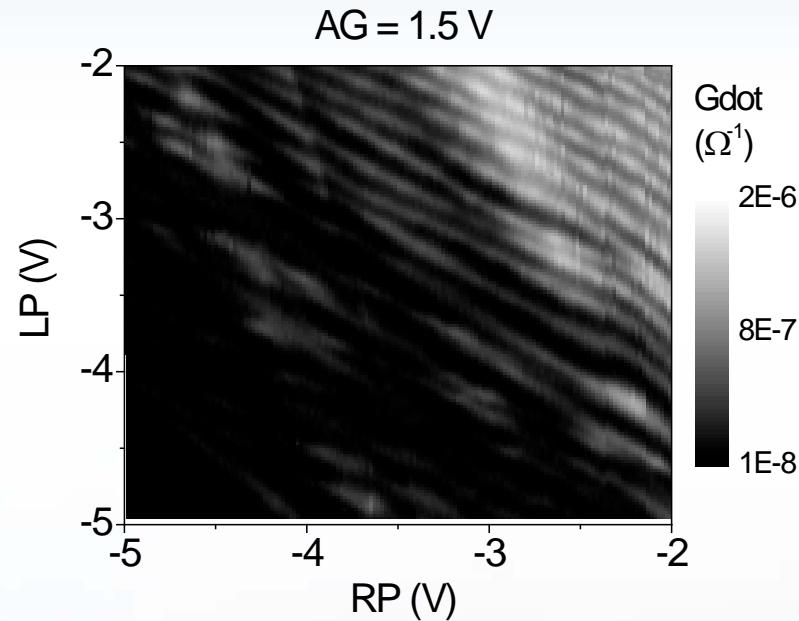
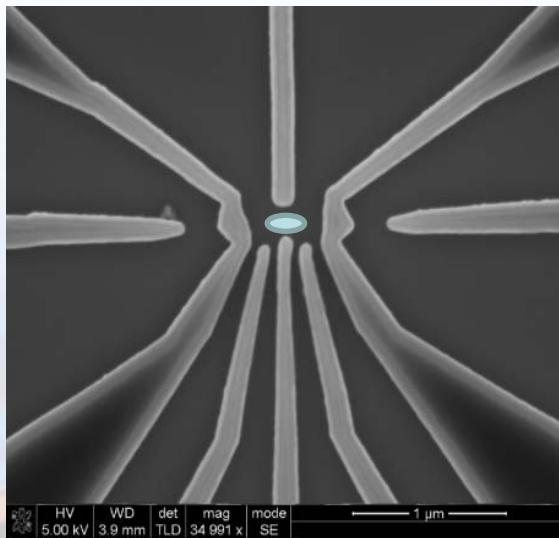
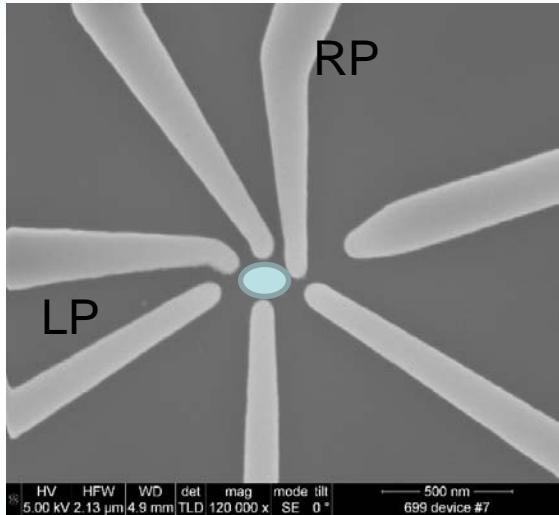
dU/dV_{SD} = -0.3825 eV/V (C_s/C = 0.3899)

Method	Width (A) [nm]	Width (B) [nm]
Triangulation to 1.5x10 ¹¹ cm ² edge	29	34
Square barrier	39	46.5



Sandia National Laboratories

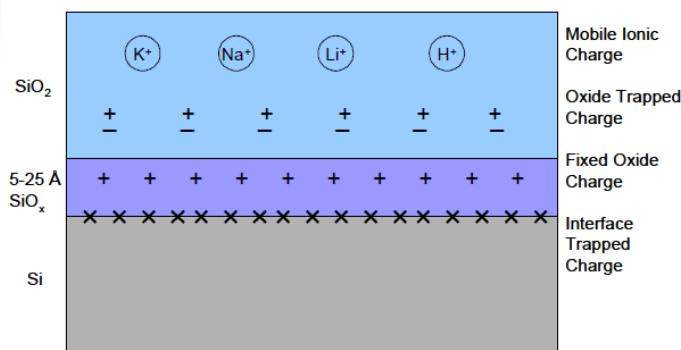
Smaller design



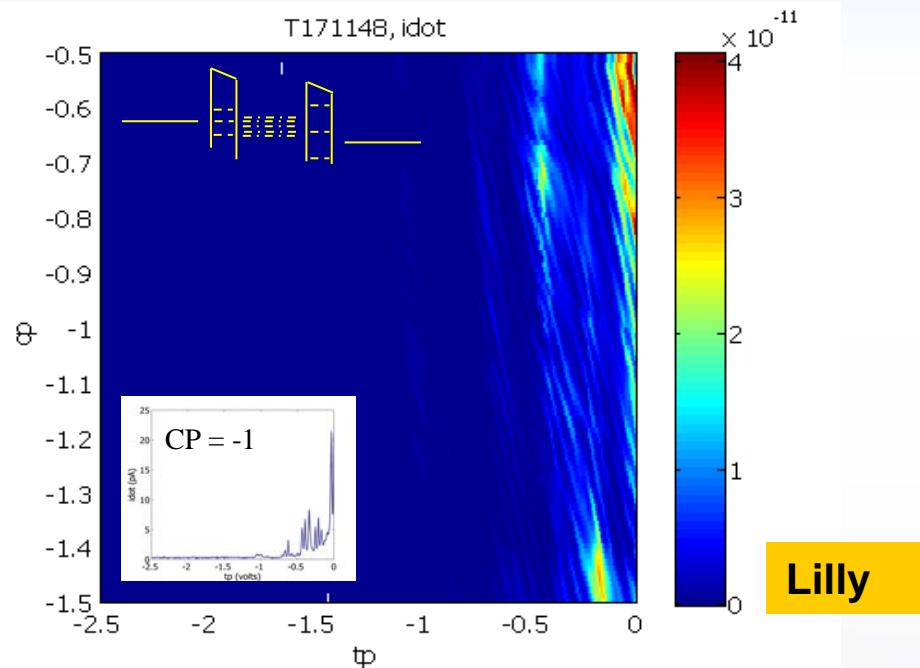
Sandia National Laboratories

Persisting doubt about MOS DQDs for qubits

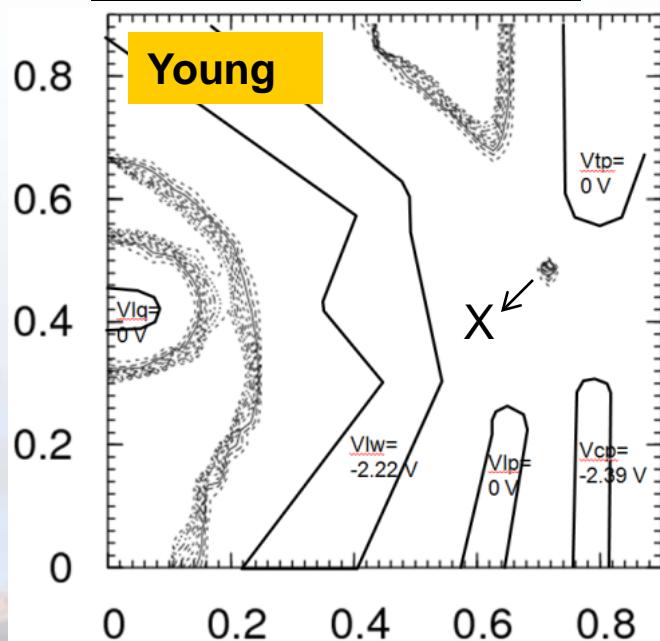
Defects



Coulomb blockade with disorder



Uncontrolled localization



Assume: DQD Area $\sim 100 \text{ nm} \times 25 \text{ nm}$

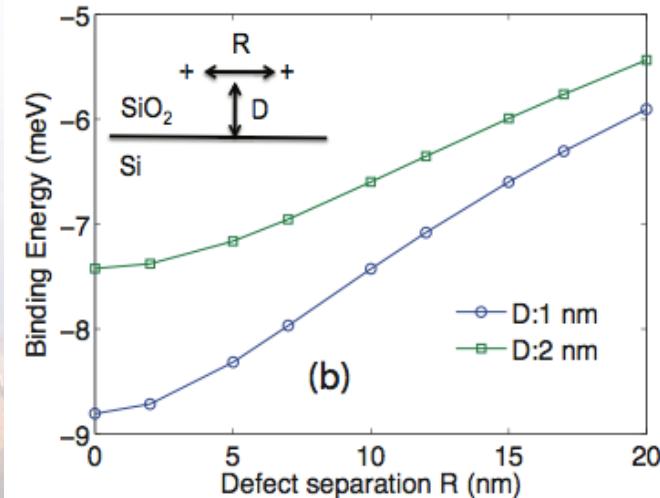
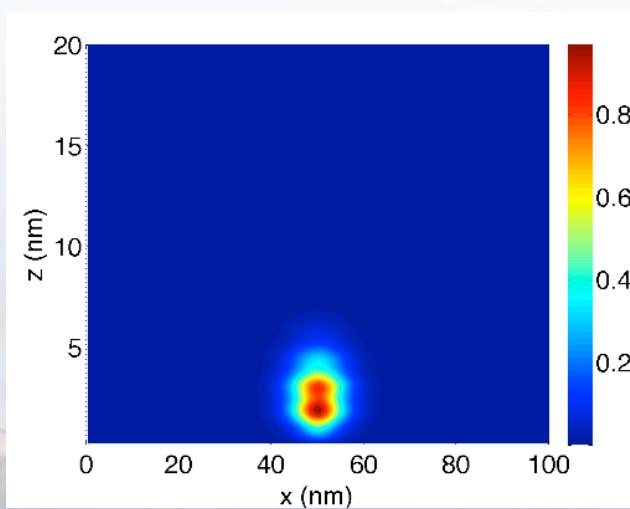
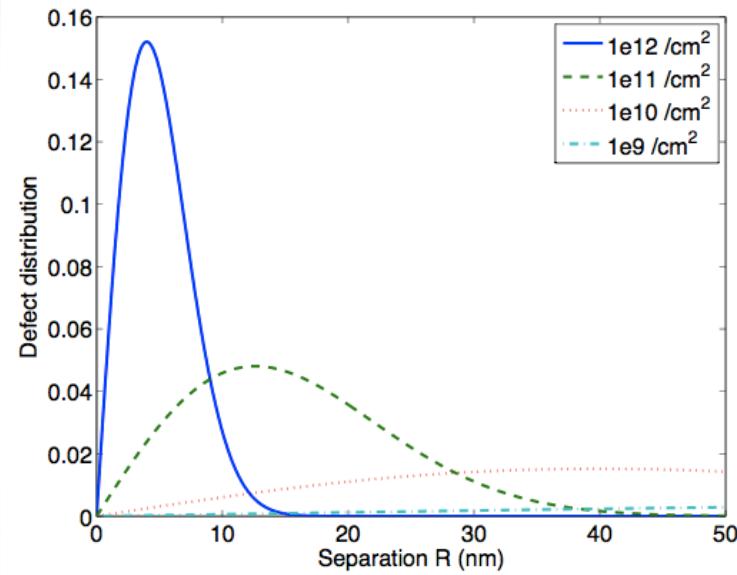
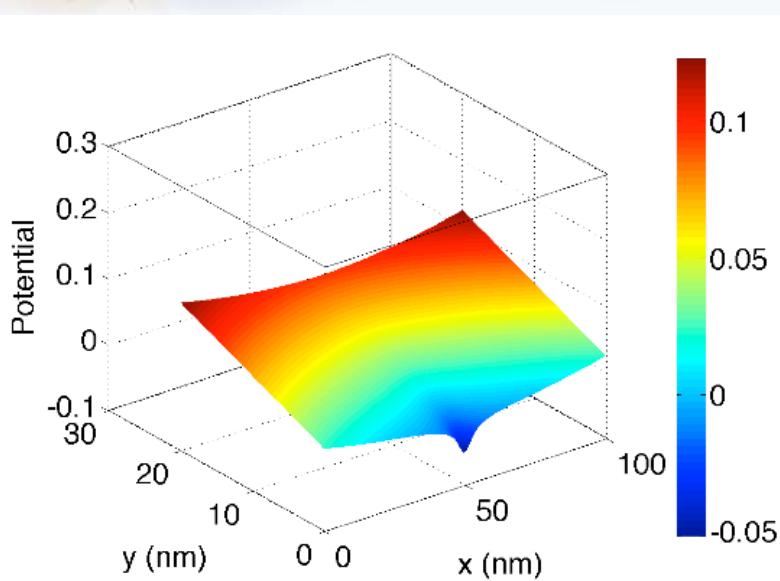
Number of defects in DQD area

$$1 \times 10^{10} \rightarrow 0.25 \text{ per QD}$$

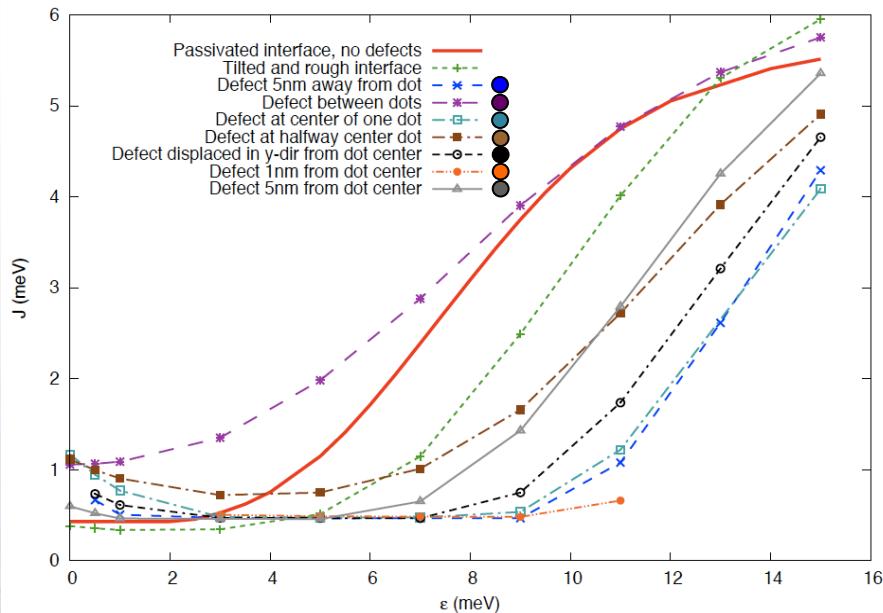
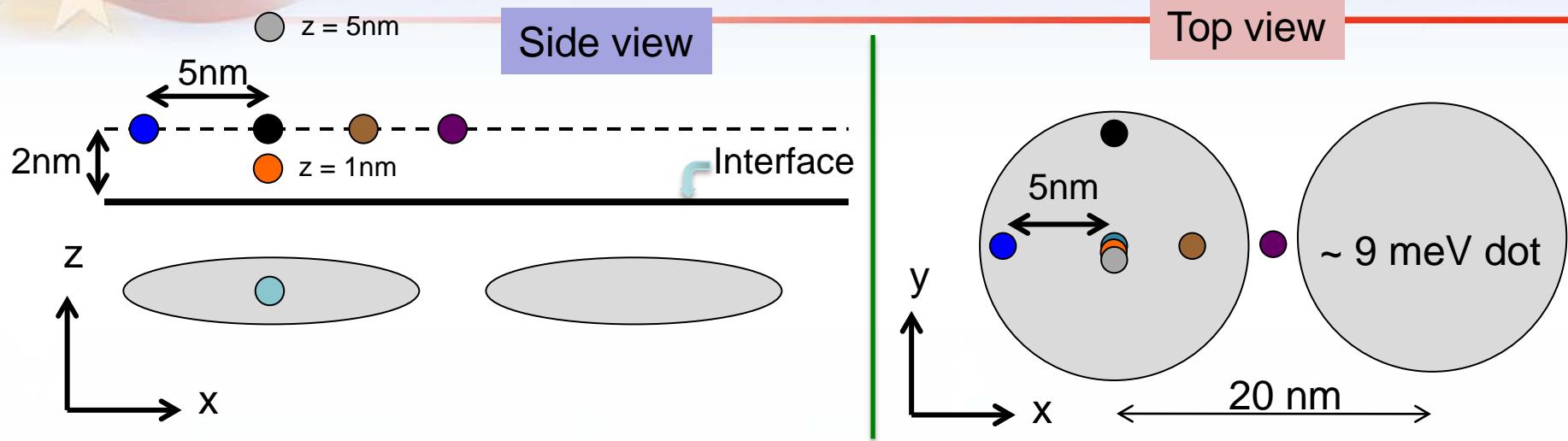
$$1 \times 10^{11} \rightarrow 2.5 \text{ per QD}$$

$$1 \times 10^{12} \rightarrow 25 \text{ per QD}$$

Implications of positive fixed charge



Implications of defects for DQD control



Conclusions:

1. Defect produces offset in detuning
2. Tunnel coupling (slope of curve) can be perturbed
3. Result is statistical variation that will require tuning.
4. Possible challenges to turning off tunneling
5. Valley physics also perturbed

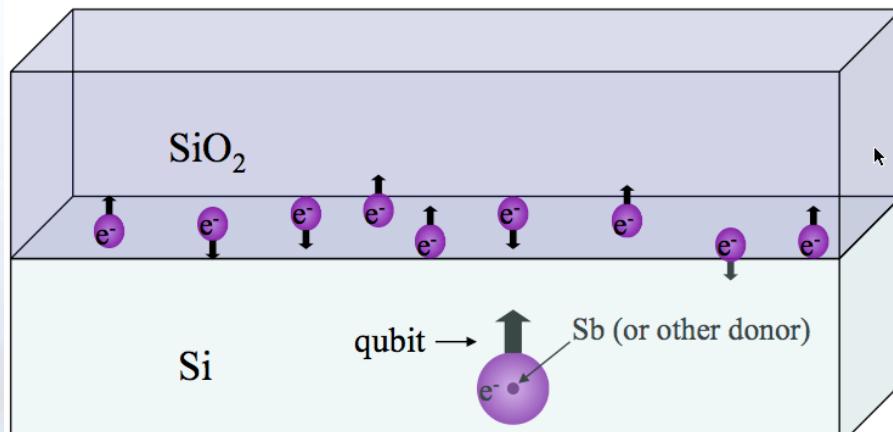


Sandia National Laboratories

Other considerations: Decoherence near Oxide

Schenkel et al. APL (2004)

Sample	Interface	Peak depth (nm)	T_1 (ms)	T_2 (ms)
120 keV	Si/SiO ₂	50	15±2	0.30±0.03
120 keV	Si—H	50	16±2	0.75±0.04
400 keV	Si/SiO ₂	150	16±1	1.5±0.1
400 keV	Si—H	150	14±1	2.1±0.1



SiO₂ from SNL (2010)

<u>d</u> (nm)	<u>T_2</u> (SNL SiO ₂)
25	490 μ s
100	520 μ s

99.95% ²⁸Si

- T_2 not as long as bulk
- Solution: sufficient B-field and low enough temperature?

Doubt: decoherence just not well understood

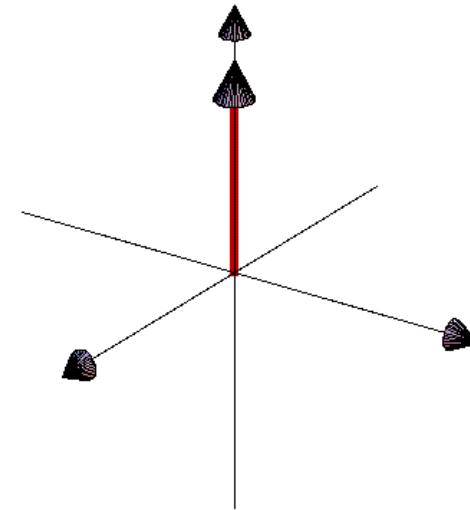
- understand problem
- eliminate decoherence



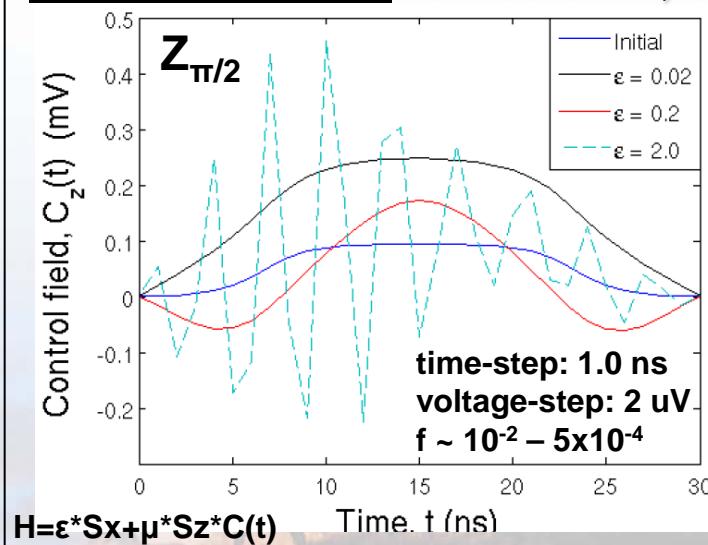
Sandia National Laboratories

More robust gates

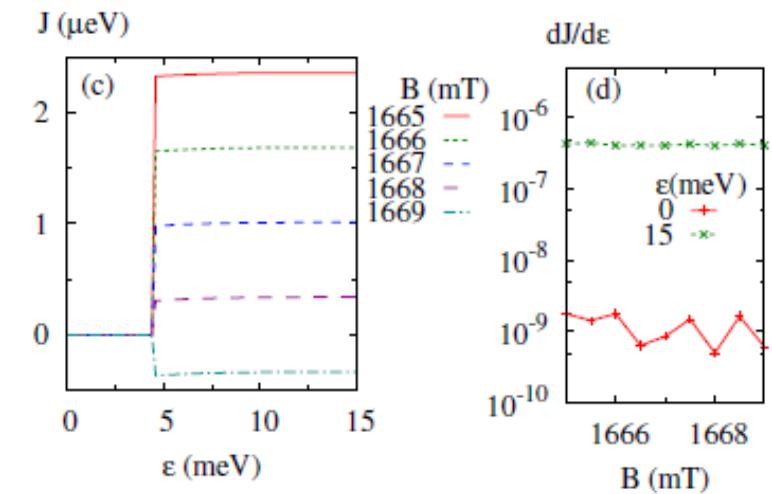
- Voltage fluctuations ($1/f \sim 5 \text{ \mu eV}$)
 - fidelity of Z gate $\sim [\dots]$
- J-flat proposal to suppress sensitivity to fluctuations
- Slow varying X-rotation during all gates due to background spins
- Hahn-echo and other DD suppresses this kind of error for idle
- Optimal control or DCG suppress X-rotation in the gate itself



Optimal Control *Grace et al., arXiv*

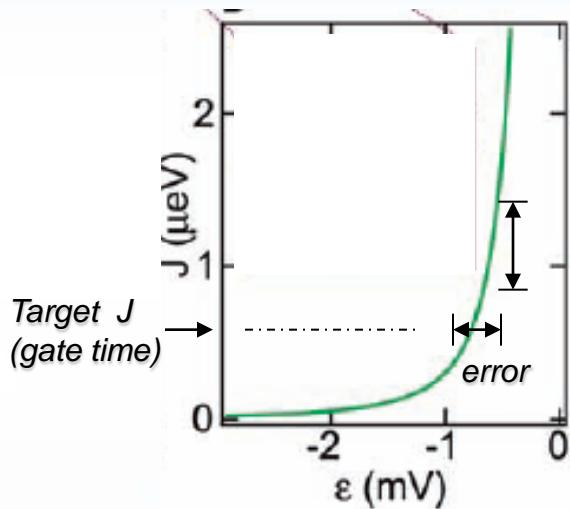


J-flat *Nielsen et al., PRB 2010*

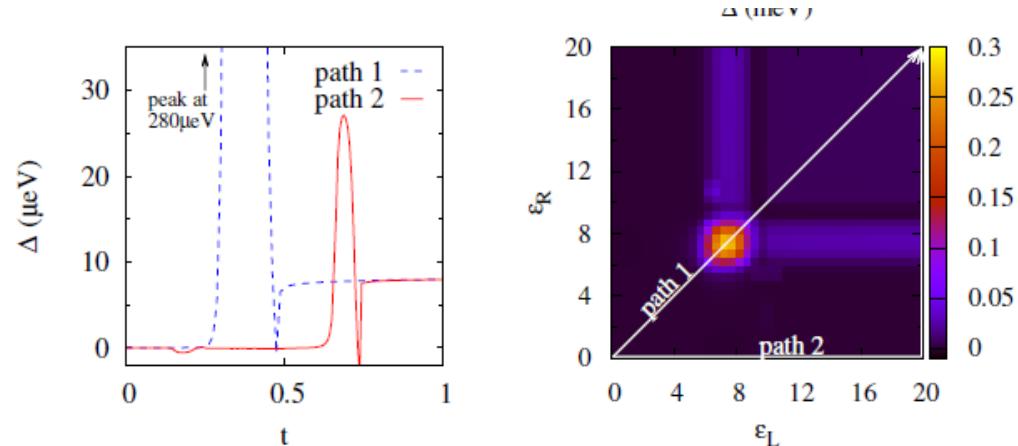
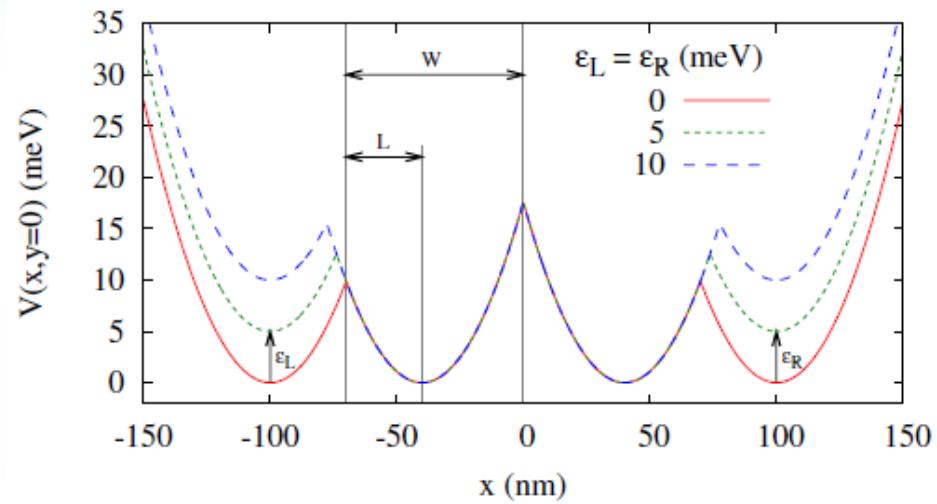


Tuned DQD Potentials for Robust CPHASE-Gate

Petta, Science 2005



Parameters: E_0, L, W, B

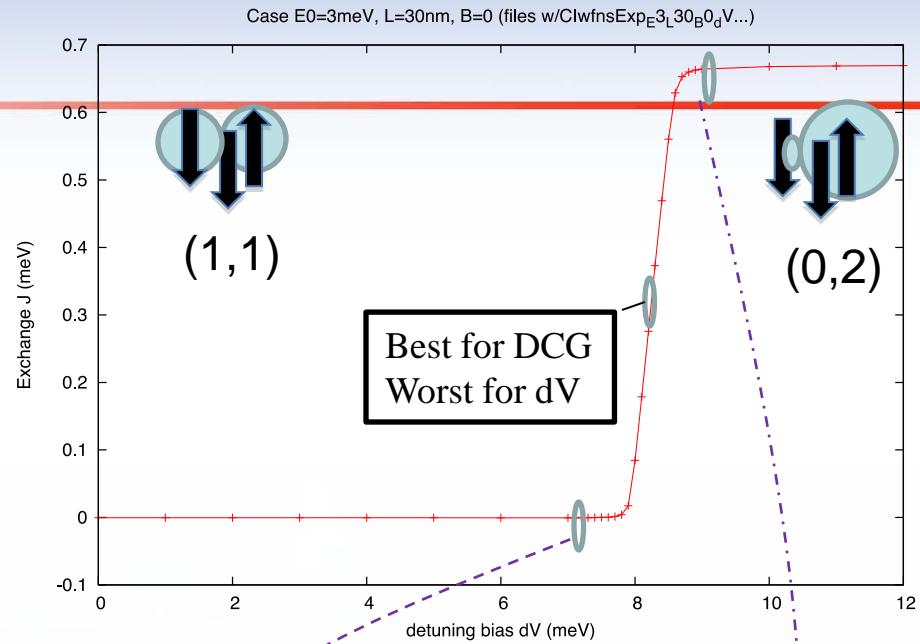


- Robust gate design desirable for CPHASE
- Effective mass calculations and CI used
- Robust regions to applied voltage do exist
- μeV coupling energies are predicted when dots are ~ 60 - 90 nm separated
- High tunability of QD potential necessary!

Value of more levels of DD: milestone scope expansion

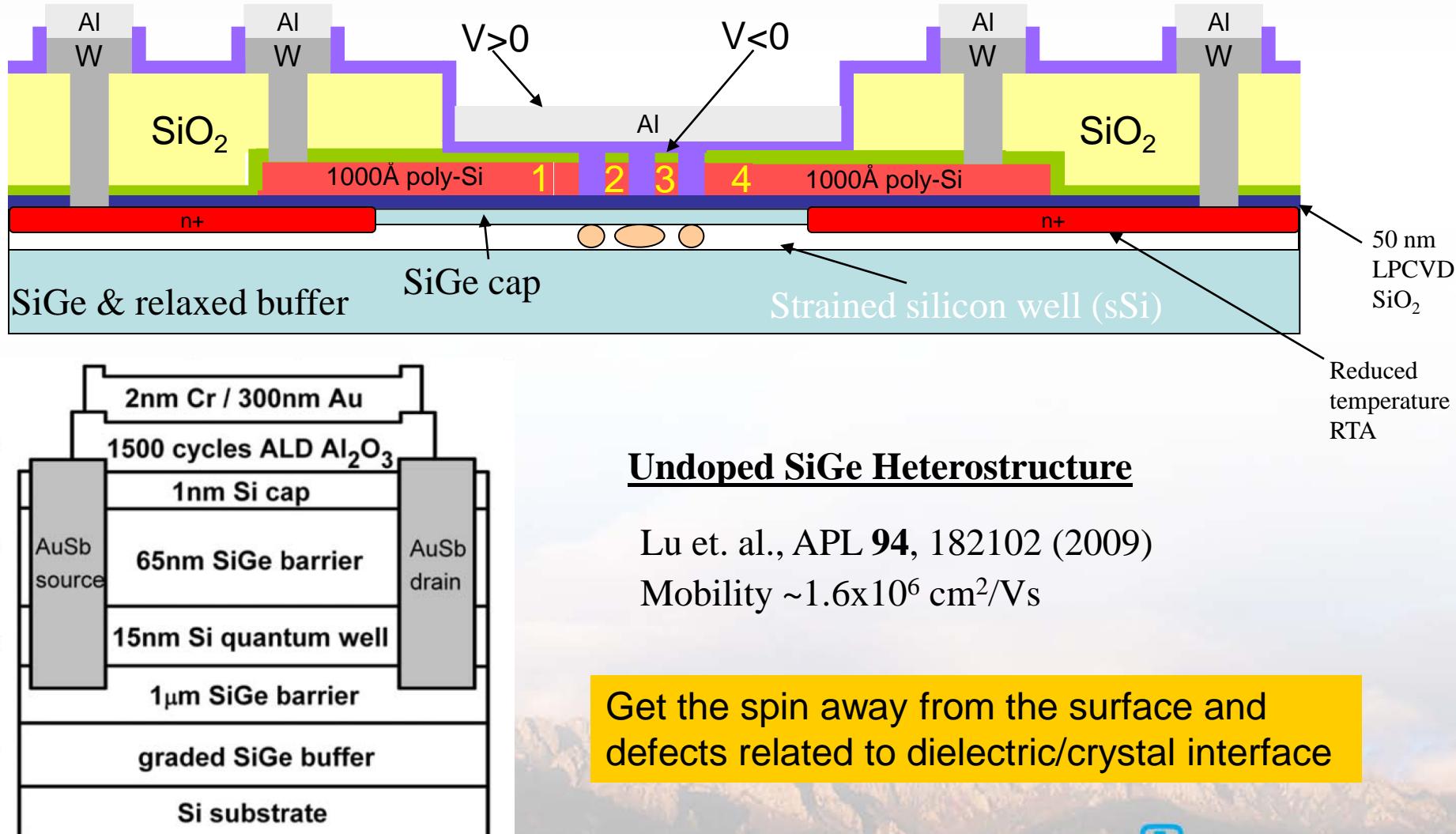
Observation:

1. X rotation during Z gate due to inhomogeneous field
2. DCG sequence to suppress unknown X rotation could be I-Z-I
3. Correlated noise might not be the same for entire sequence I – Z – I



Sandia National Laboratories

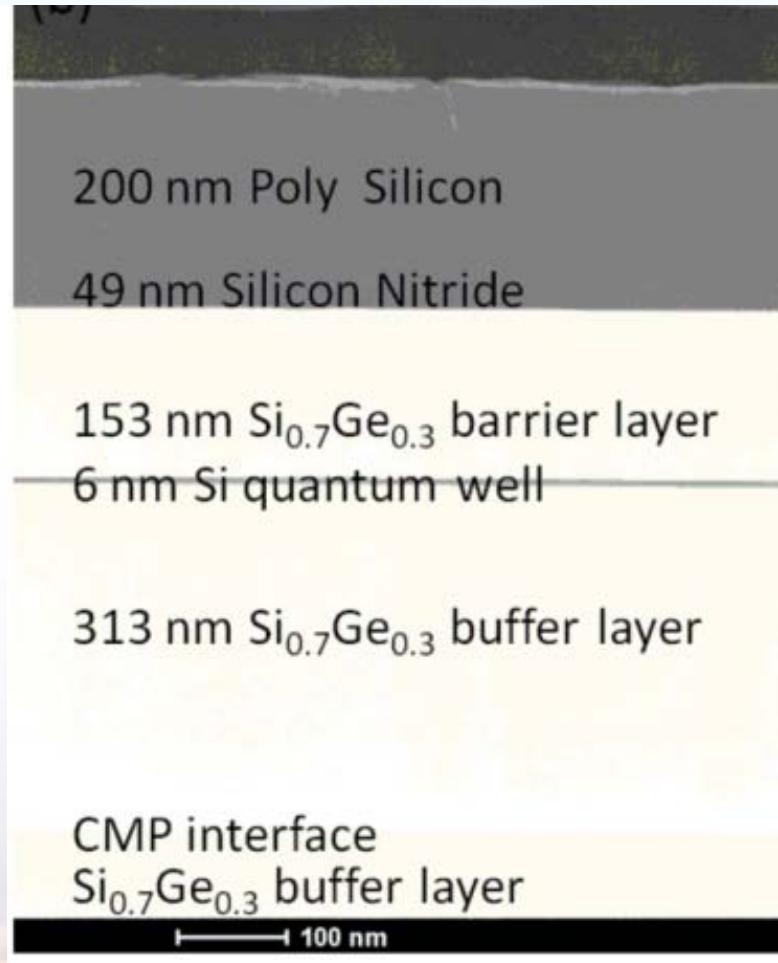
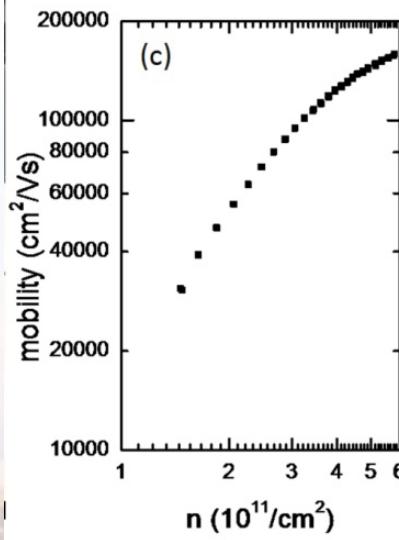
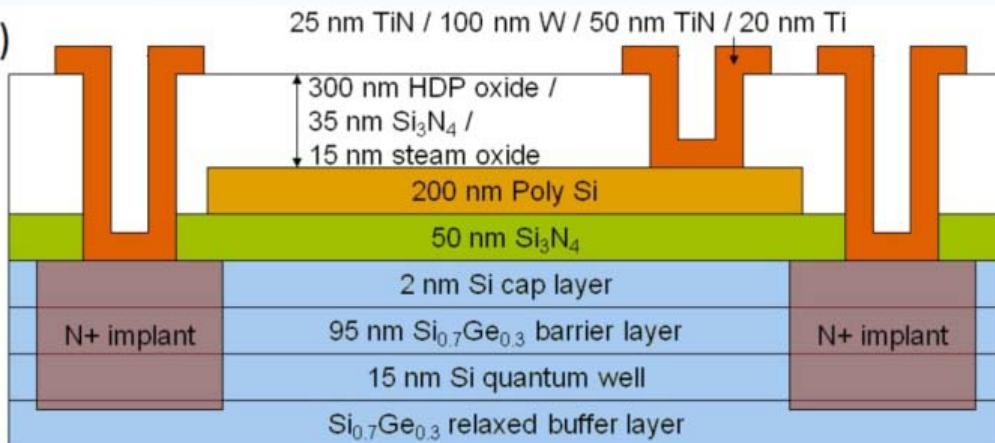
Enhancement Mode SiGe/sSi: High Mobility & Modular Change to MOS Flow



Sandia National Laboratories

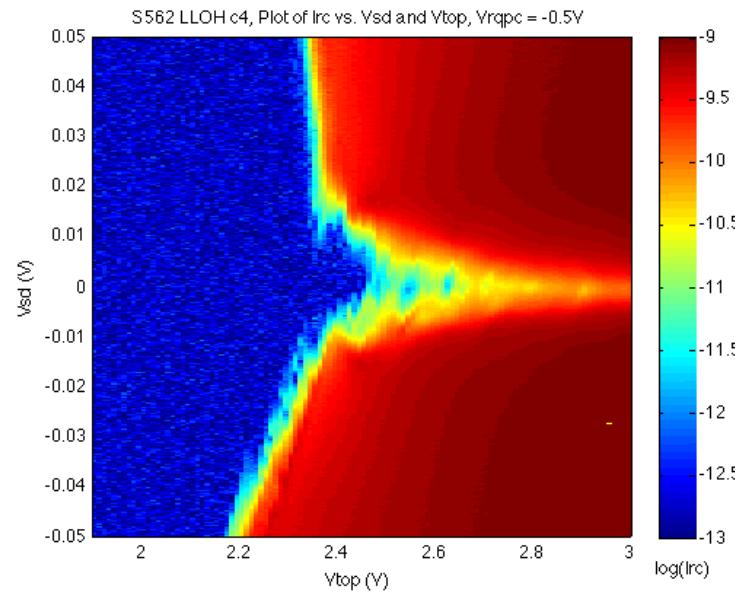
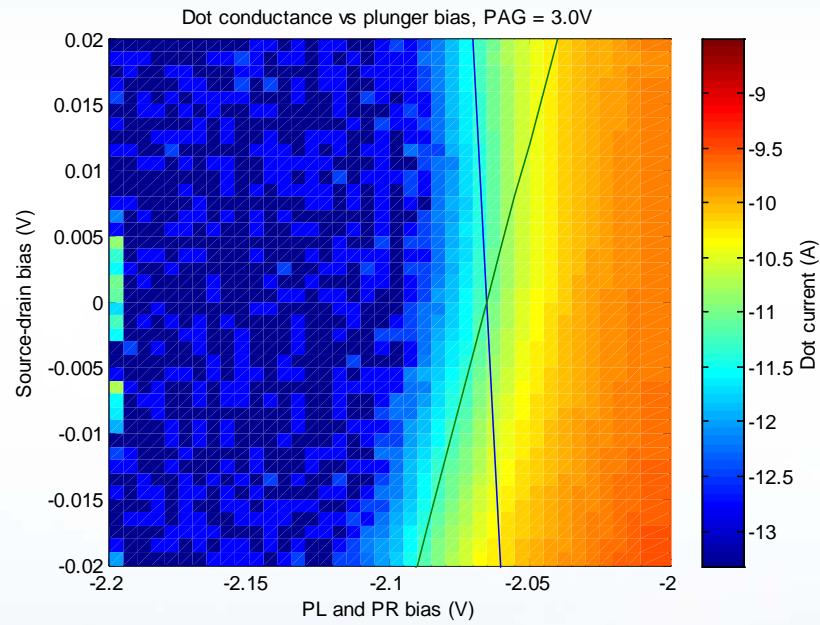
Back to the fab: SiGe/sSi

(a)



- Modifications:
 1. Substrate
 2. Gate dielectric
 3. Implant & anneals
- Questions:
 1. Ge/Si diffusion
 2. Surface pinning
 3. Mobility

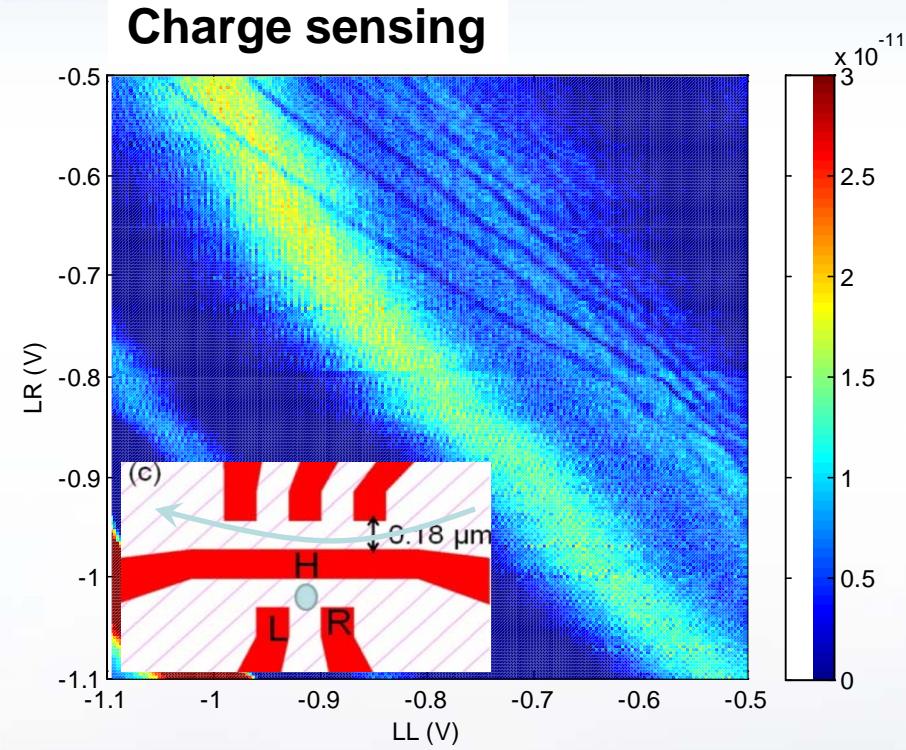
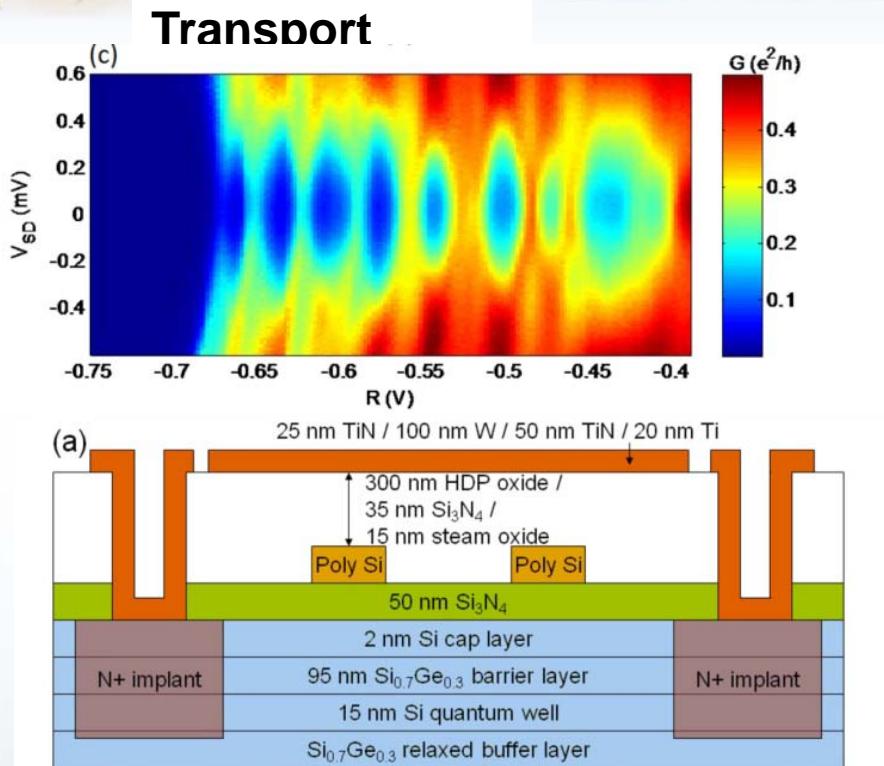
Smooth SiGe barriers at 4K



Biggest source of uncertainty is choice of fitting parameter V_0 (point of linear expansion)

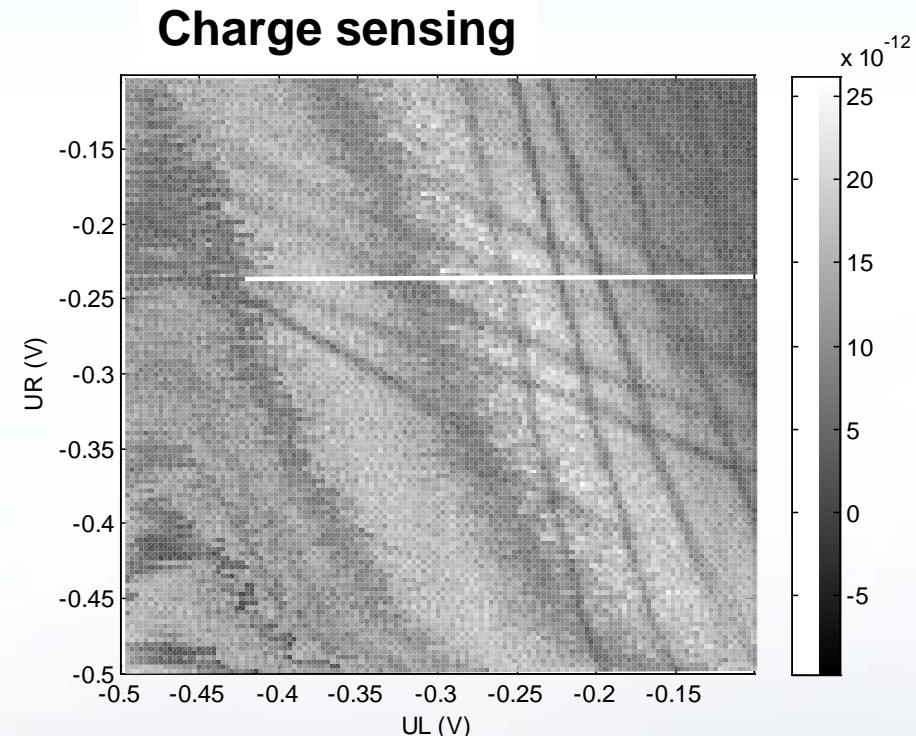
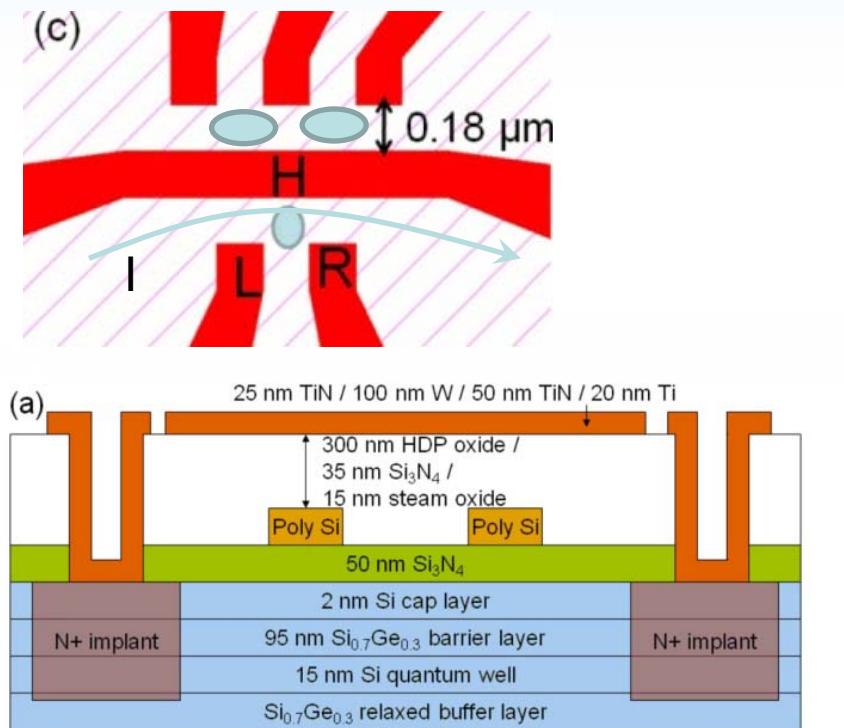
V_{dc} (mV)	Δ (meV)	w (nm)
+20	$35 +/- 8$	$15 +/- 2$
+10	$34 +/- 8$	$16 +/- 2$
0	$35 +/- 8$	$15 +/- 2$
-10	$37 +/- 8$	$13 +/- 1$
-20	$35 +/- 8$	$12 +/- 1$

Charge sensing: last transition



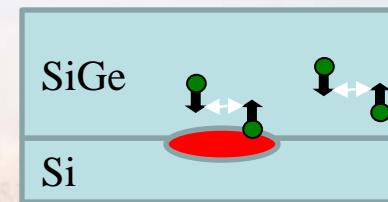
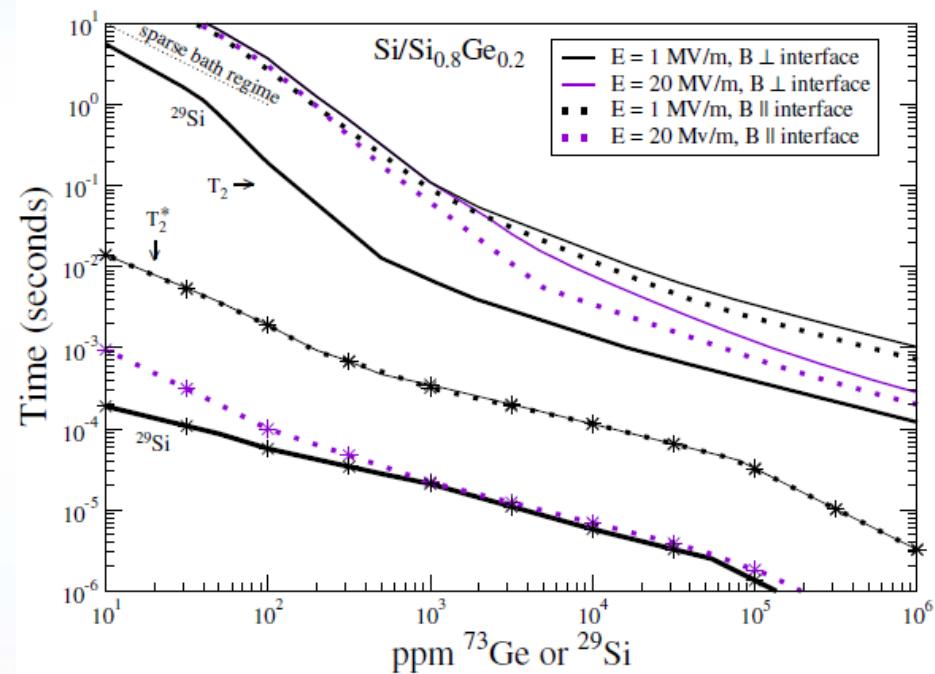
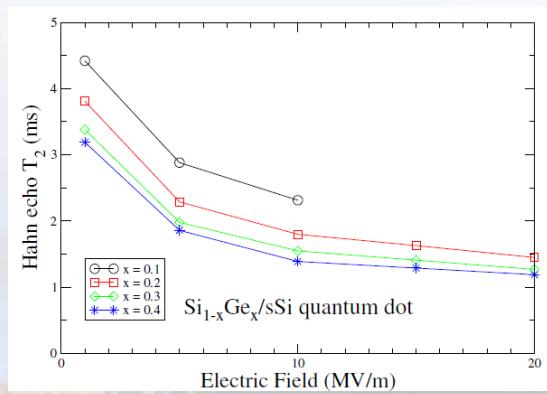
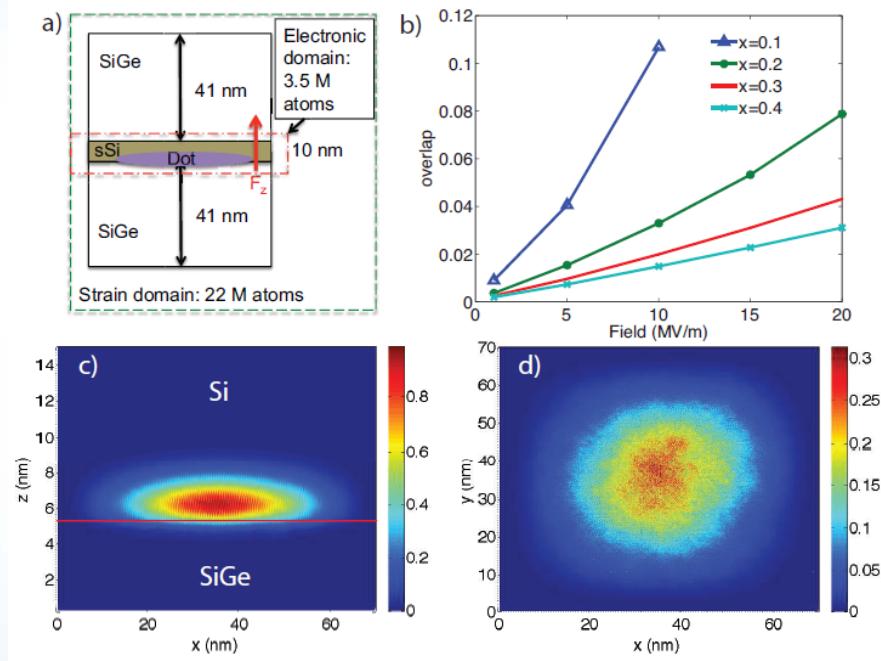
- Opposite channel used as charge sensor
- Last transition in region of high sensitivity of sensor
 - looks like the last electron
- DQD tuning also possible (charge sensed)
- Problem: charge stability

Charge sensing: last transition



- Double top gated quantum dot w/ DUV lithography
- Relatively regular CB observed w/ small charging energy

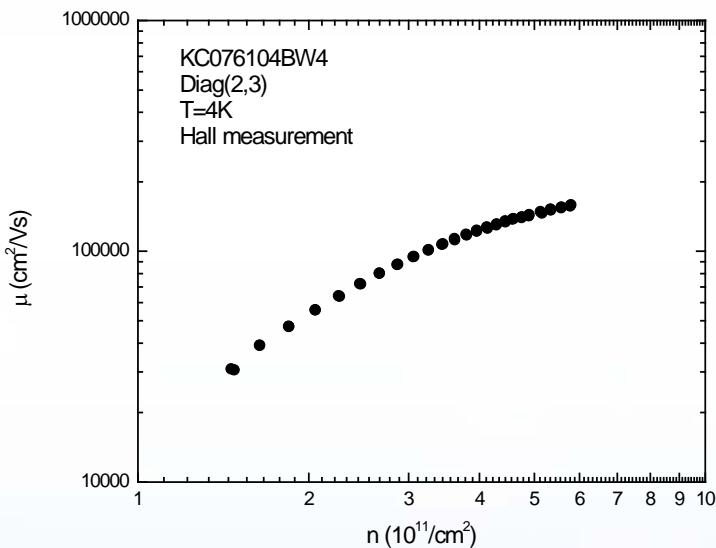
Silicon T2 vs. SiGe/sSi (unenriched)



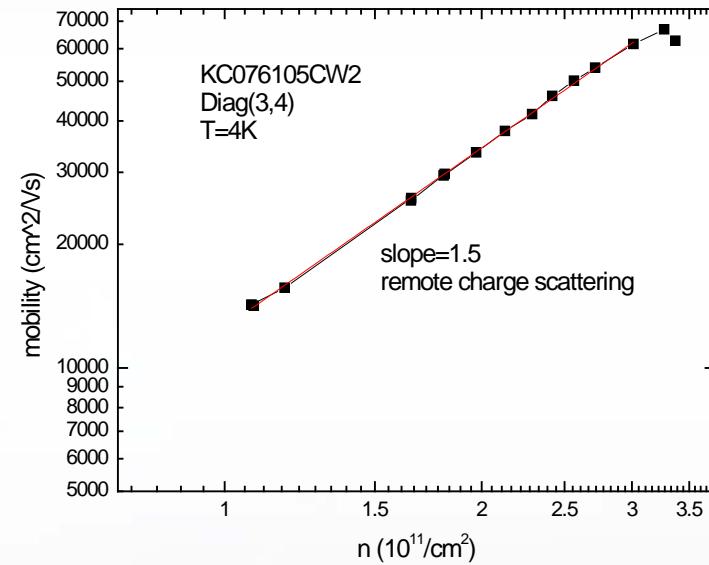
Sandia National Laboratories

Reduced SiGe barrier thickness for increased stability

150 nm SiGe barrier (not stable)

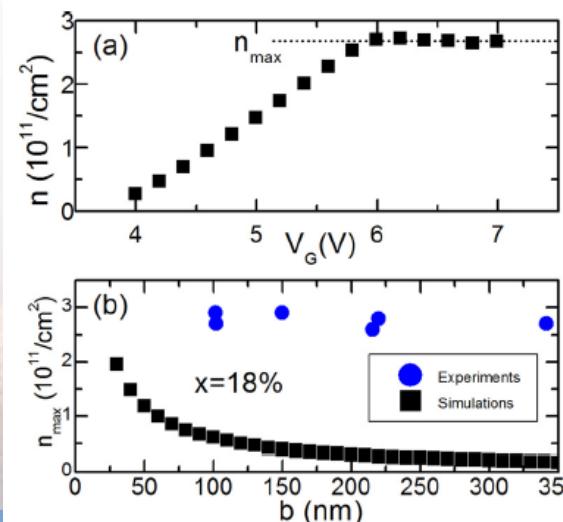
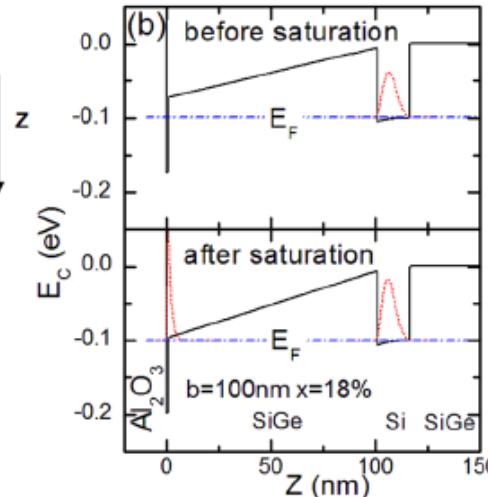
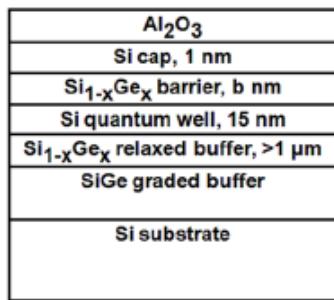


35 nm SiGe barrier (stable)

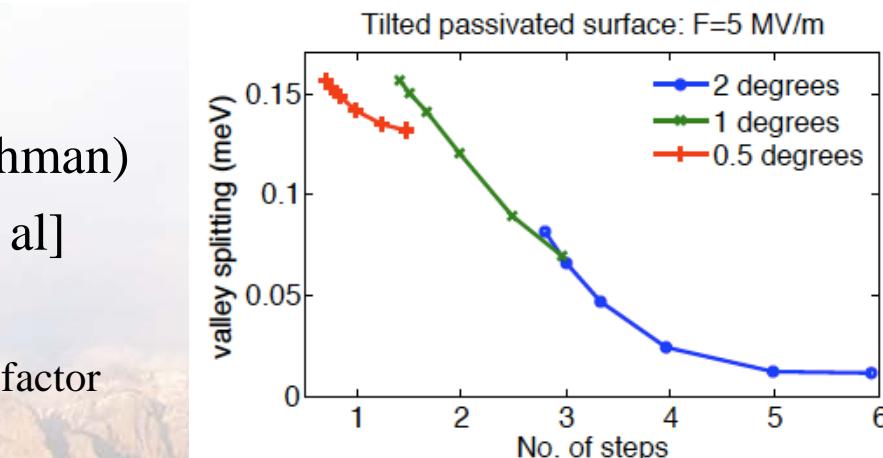
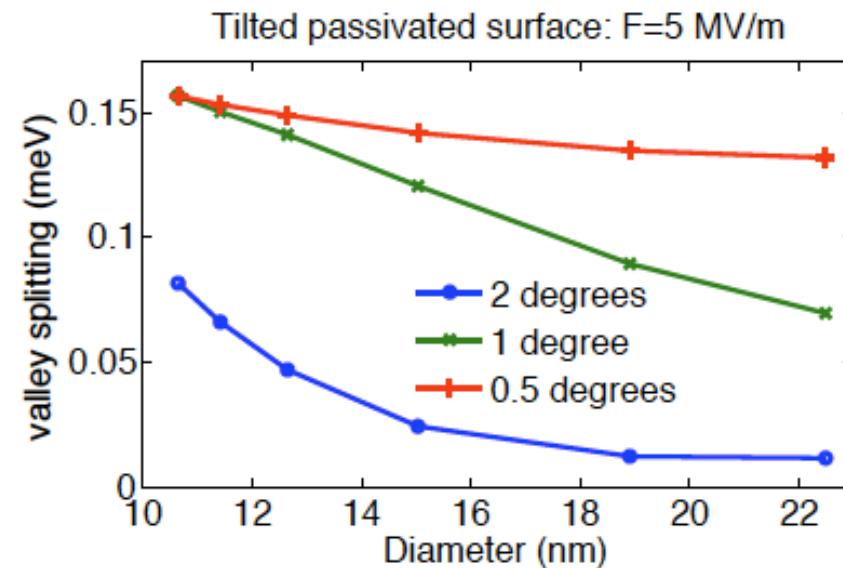
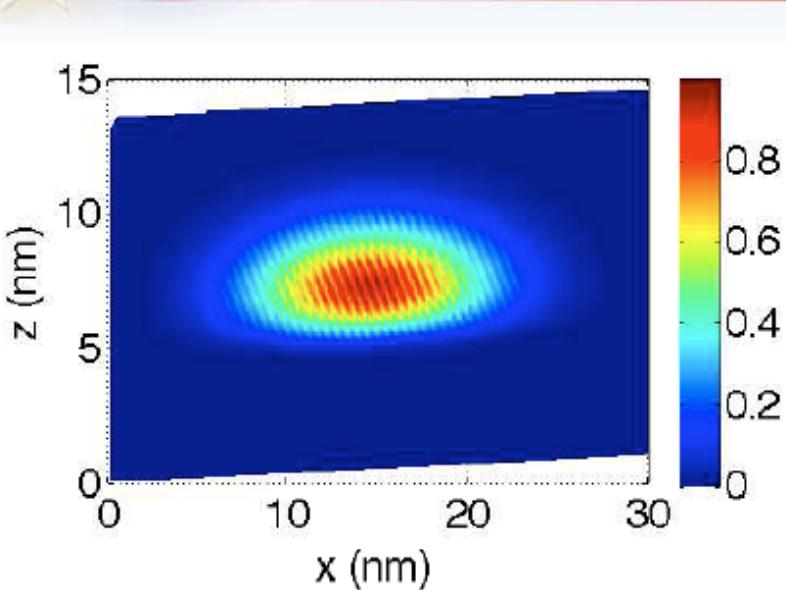


T. Lu, APL 99 (2011)

(a)



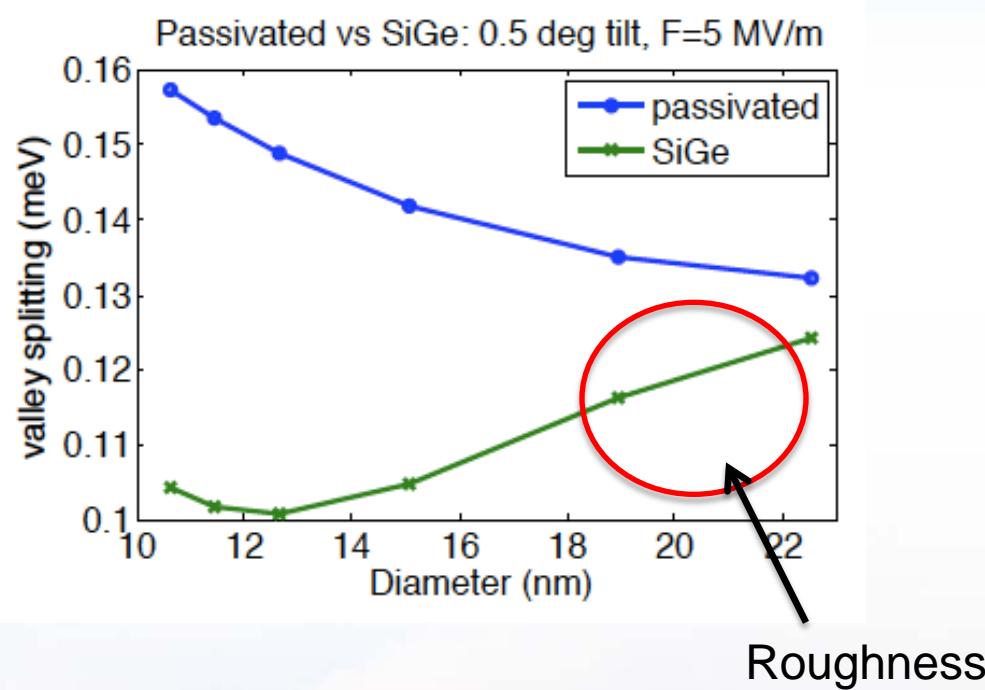
Few electron energies in SiGe



- Modeling of valley splitting at SNL
- Atomistic tight binding calculations (R. Rahman)
- Step edge dependence observed [Friesen et al]
- Calculations done for QD
 - Number of step edges appears to be determining factor



Valley physics still to better understand



- Evidence suggests that VS can be big enough
- Ge and Ge profile dependence not well understood
- Big phase space with E-field & processing





Summary

- Measurements and theory suggest very long T2 possible with enrichment and high purity [Witzel et al. PRL 2010]
- Tunable DQDs measured with transport [Tracy et al., APL 2010]
- Transport suggests new MOS design can achieve N=1
 - capacitances are consistent with CAD simulated N=1 capacitances
- Charge sensed MOS DQDs demonstrated
 - Balancing charge sensing, sensitivity and N=2 (DQD) is challenging
- CAD simulation tool being developed and calibrated to assist in design (smaller) and analysis
 - Good tunneling model for CAD needed for design
- Square barrier, WKB tunneling model produces self-consistent results with xpt. fits
- CI/TB calculations indicate positive charge defects can localize the DQD electrons, but tuning can work-around many defects
- J and CPHASE flats are predicted theoretically and are potentially more robust operation points [Nielsen et al., PRB and arXiv]
- T2 at surface near oxides is still not well established
- DCG might be inconsistent with J flat
- SiGe enhancement mode quantum dots have been developed (just get away from defects)
 - Measurements are consistent with charge sensed few electron QD and DQDs [Lu et al., APL 2011]
 - Barriers look cleaner
 - Sudden shut-off in 150K mobility material, thinner SiGe barrier, 70K mobility, has fewer abrupt shut-offs
 - Ge isotopes are predicted to limit T2 [Witzel et al., submitted PRB rapid]





Acknowledgements

- The technical teams
 - Silicon quantum dot:** M. Lilly, N. Bishop, S. Carr, T.-Z. Lu, L. Tracy, K. Nguyen, T. Pluym, J. Dominguez, J. Wendt, J. Stevens, B. Silva, E. Bower, R. Gillen
 - Donor and donor-dot:** E. Bielejec, E. Bussmann, D. Perry, B. McWatters, A. MacDonald
 - Device modeling:** R. Muller, R. Young, W. Witzel, E. Nielsen, R. Rahman, K. Young, J. Verley
 - Cryogenic electronics:** T. Gurrieri, J. Levy, R. Young, J. Hamlet, K. Barkley
 - Architecture and quantum error correction:** A. Ganti, M. Grace, W. Witzel, U. Onunkwo, A. Landahl, C. Phillips, R. Carr, T. Tarman
- Joint research efforts with external community:
 - U. Wisconsin (M. Eriksson, D. Savage, M. Friesen, R. Joynt)
 - Australian Centre for Quantum computing Technology (L. Hollenberg, D. Jamieson, M. Simmons, A. Dzurak, A. Morello)
 - Princeton University (S. Lyon)
 - NIST (N. Zimmerman)
 - U. Maryland (S. Das Sarma, M. Peckerar)
 - Lawrence Berkeley National Labs (T. Schenkel)
 - National Research Council (A. Sachrajda)
 - U. Sherbrooke (M. Pioro-Ladriere)

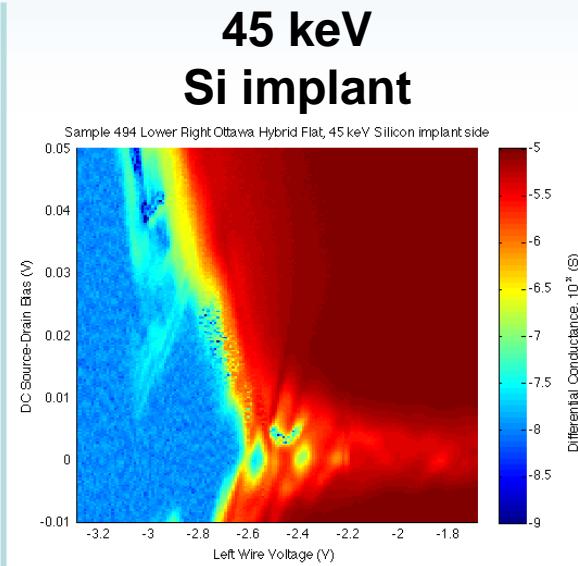
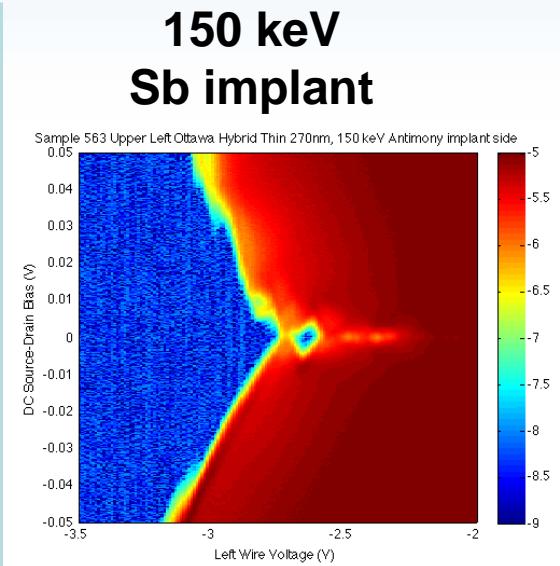
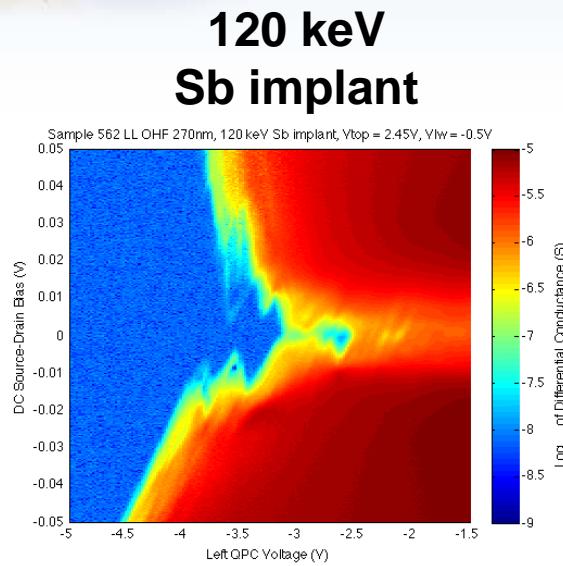




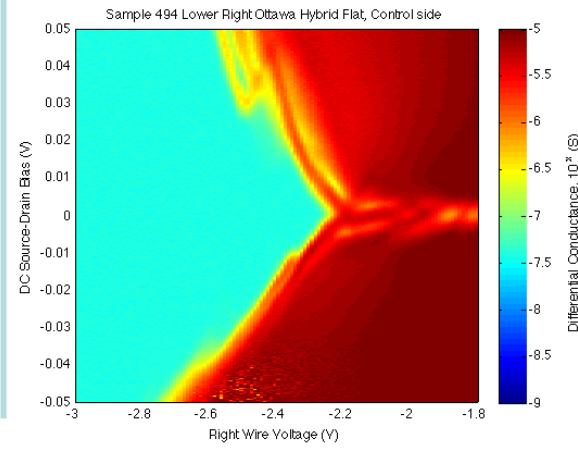
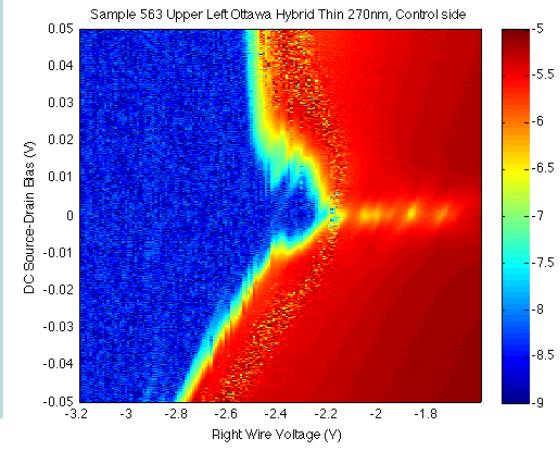
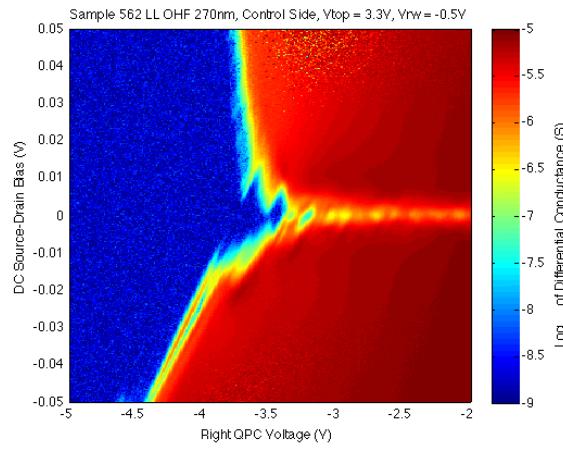
Sandia National Laboratories

Statistical analysis of implanted tunnel barriers

Implant



Control

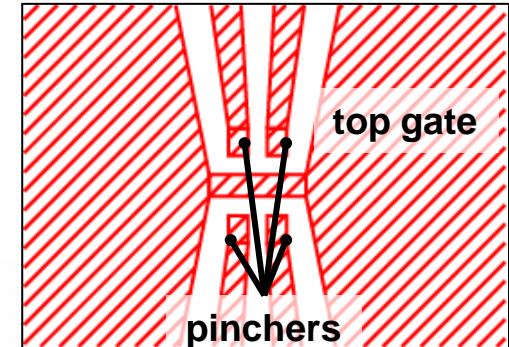
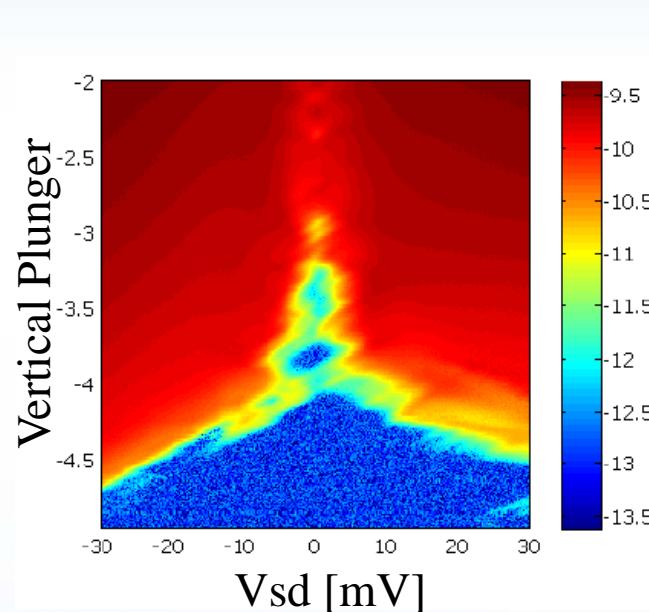
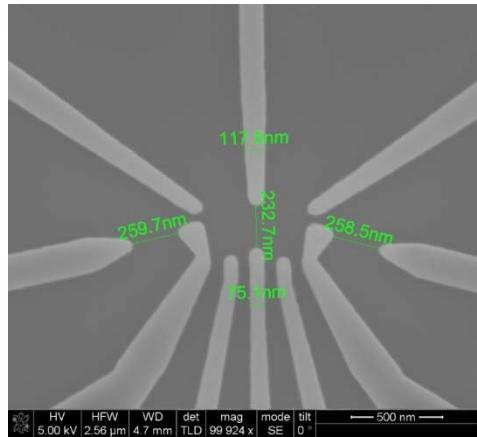


Donor signature difficult to find, but very useful for modeling tunnel barrier.

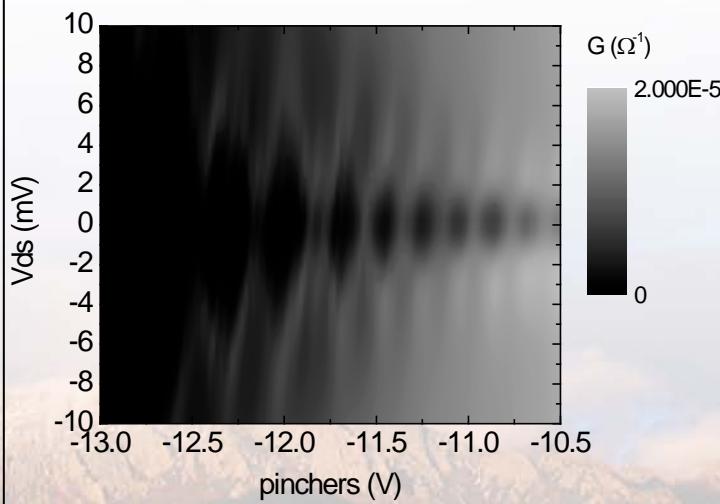


Sandia National Laboratories

Qualitative differences between disorder in different structures



(K. Eng & L. Tracy)
 $V_{tg} = 4$ V
 $W_g = -75$ V
 $T = 0.25$ K

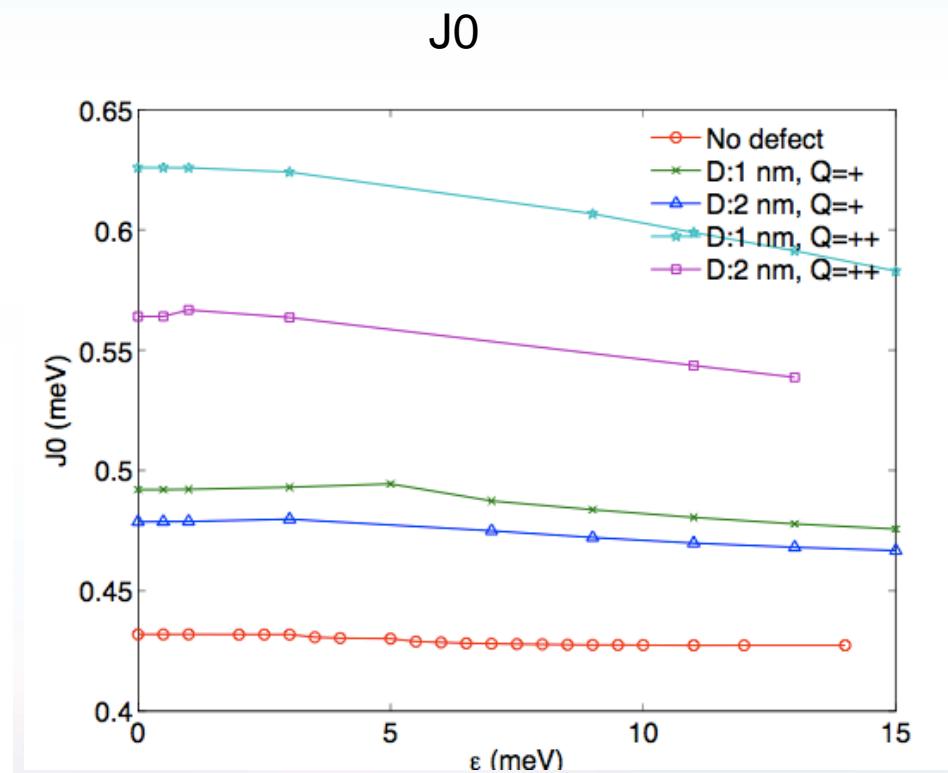
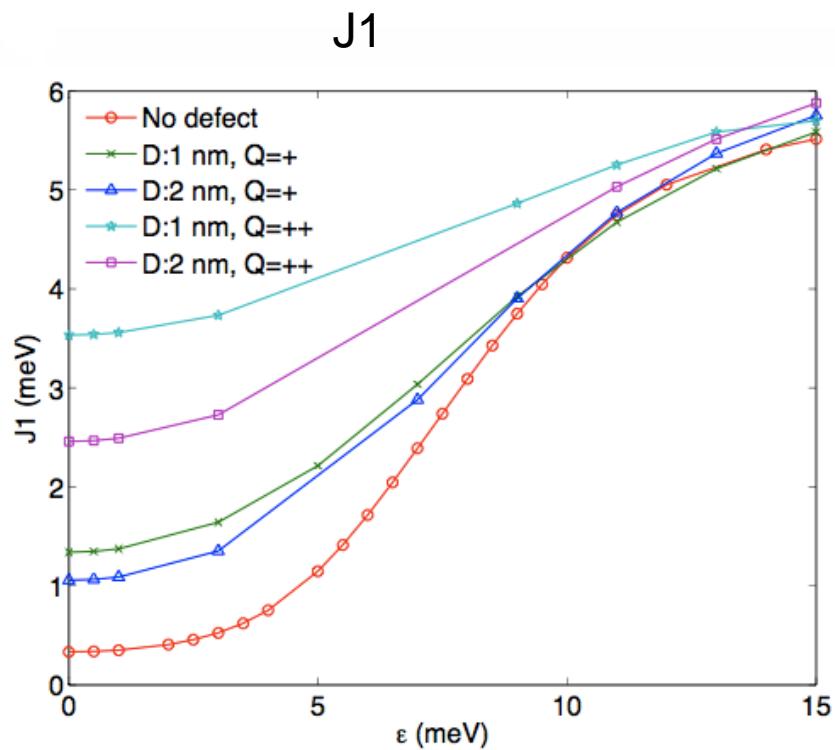
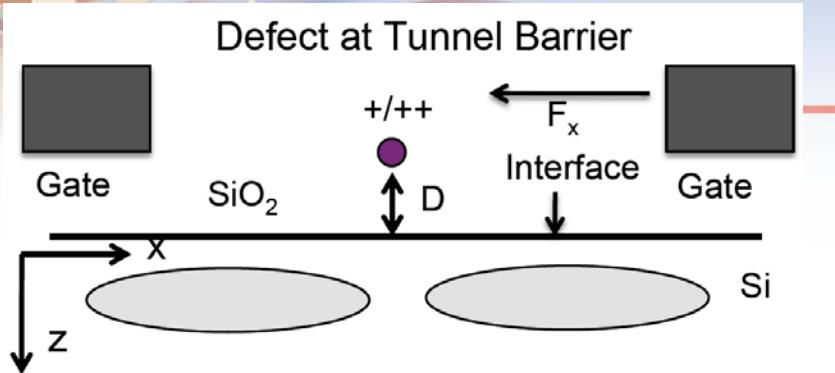


- Common in MOS for charging energy to rapidly increase as $N \Rightarrow 1$
- Charge sensing also detects outlier(s)
- Large area devices produce small dot charging energies?



Sandia National Laboratories

Fig. 3a) Defect at Tunnel barrier

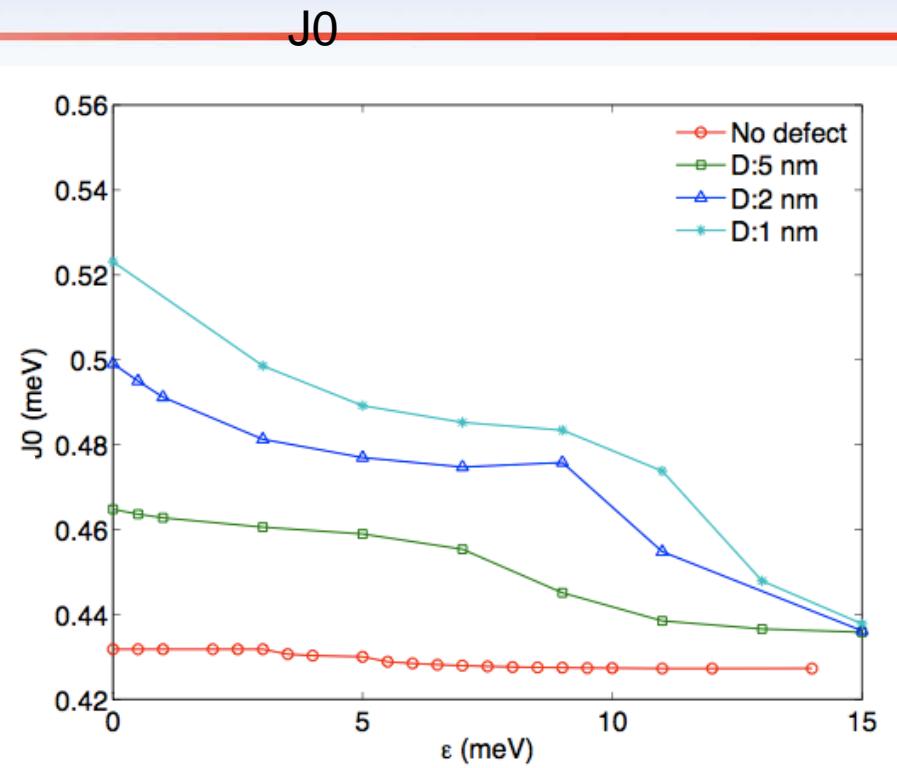
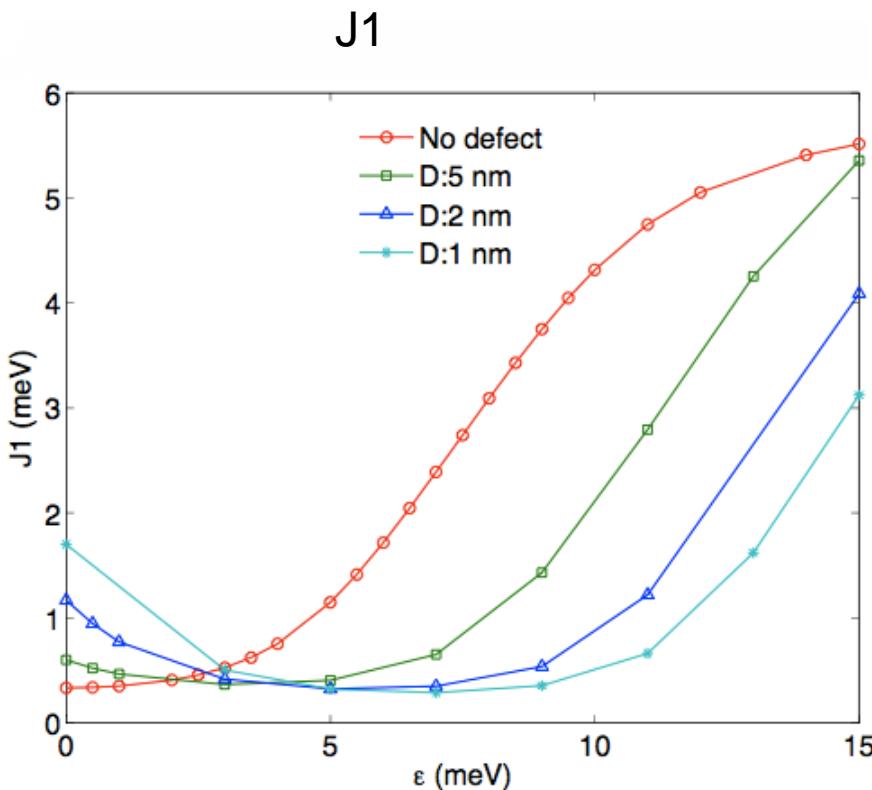
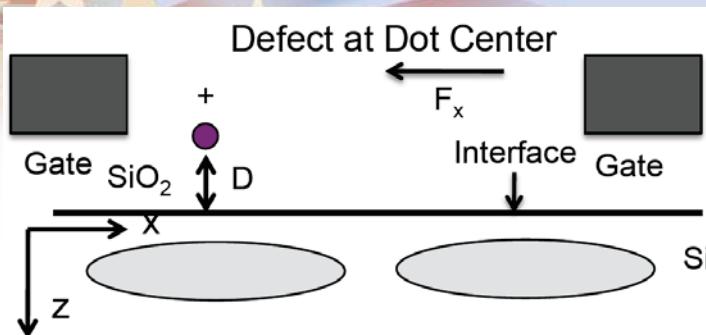


Stronger the effect of the defect potential, the greater is the valley splitting, hence the curves move up



Sandia National Laboratories

Fig. 3b) Defect at center of one dot

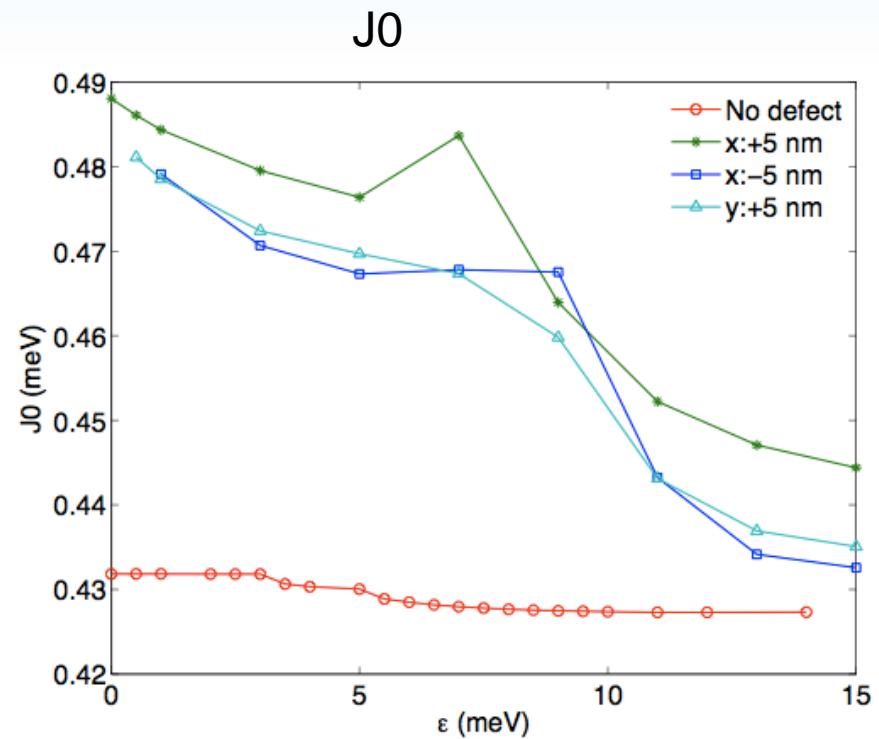
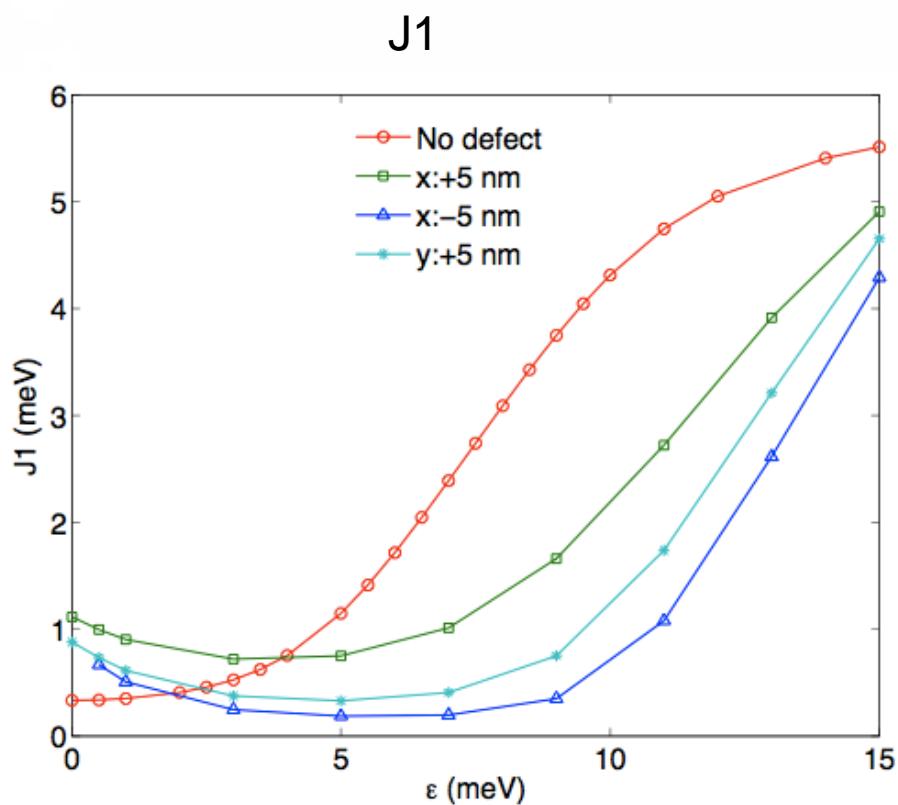
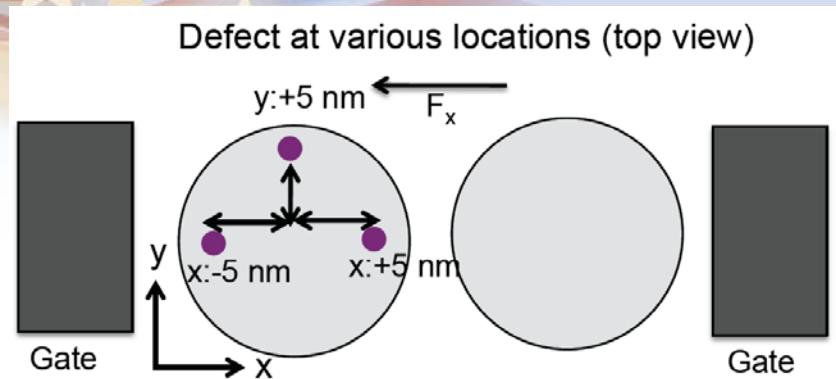


Defect cause VS to be different in two dots, hence the slope of the curve. The “hump” is a bit mysterious and doesn’t seem to be a numerical artifact.



Sandia National Laboratories

Fig. 3c) Defect at various locations



Same effect: Asymmetric VS



Sandia National Laboratories